

HP ProLiant BL660c Gen8 Server Blade User Guide

Abstract

This document is for the person who installs, administers, and troubleshoots servers and storage systems. HP assumes you are qualified in the servicing of computer equipment and trained in recognizing hazards in products with hazardous energy levels.



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Contents

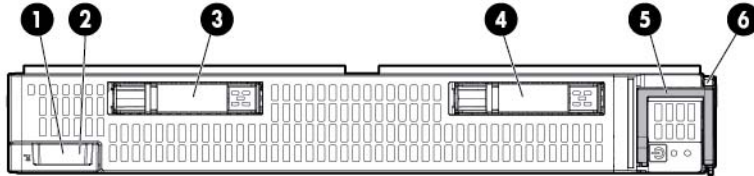
Component identification	6
Front panel components	6
Front panel LEDs and buttons	6
Drive LED definitions	7
System board components	8
Mezzanine connector definitions	9
DIMM slot locations	9
Tool locations	10
HP c-Class Blade SUV Cable	10
Operations	12
Power up the server blade	12
Power down the server blade	12
Remove the server blade	13
Remove the access panel	14
Remove a drive	14
Removing DIMM baffles	14
Remove the center DIMM baffle	14
Remove the left DIMM baffle	15
Remove the right DIMM baffle	16
Remove the front panel/drive cage assembly	16
Remove the FBWC capacitor pack	17
Setup	19
Installing an HP BladeSystem c-Class enclosure	19
Preparing the enclosure	19
Installing interconnect modules	22
Interconnect bay numbering and device mapping	23
Connecting to the network	24
Installing server blade options	24
Installing a server blade	24
Assembling a full height blank	25
Completing the configuration	26
Hardware options installation	27
Introduction	27
Drive option	27
Processor option	28
Memory options	32
HP SmartMemory	33
Memory subsystem architecture	33
Single-, dual-, and quad-rank DIMMs	34
DIMM identification	35
Memory configurations	35
General DIMM slot population guidelines	37
Installing a DIMM	38
FBWC capacitor pack options	39

Mezzanine card option	40
HP Trusted Platform Module option	42
Installing the Trusted Platform Module board	43
Retaining the recovery key/password	44
Enabling the Trusted Platform Module.....	45
Cabling	46
Cabling resources	46
FBWC capacitor pack cabling	46
Using the HP c-Class Blade SUV Cable	47
Connecting locally to a server blade with video and USB devices.....	48
Accessing a server blade with local KVM	48
Accessing local media devices	49
Software and configuration utilities	50
Server mode	50
Server QuickSpecs	50
HP iLO Management Engine	50
HP iLO	50
Intelligent Provisioning.....	52
HP Insight Remote Support software	54
Scripting Toolkit	54
HP Service Pack for ProLiant	55
HP Smart Update Manager.....	55
HP ROM-Based Setup Utility	55
Using RBSU	56
Auto-configuration process.....	56
Boot options	57
Configuring AMP modes	57
Re-entering the server serial number and product ID	57
Utilities and features	58
Array Configuration Utility.....	58
Option ROM Configuration for Arrays	59
ROMPaq utility.....	59
Automatic Server Recovery	59
USB support.....	59
Redundant ROM support	60
Keeping the system current	60
Drivers	60
Software and firmware.....	61
Version control.....	61
HP Operating Systems and Virtualization Software Support for ProLiant Servers.....	61
Change control and proactive notification	61
Troubleshooting	62
Troubleshooting resources	62
Battery replacement	63
Regulatory compliance notices	64
Regulatory compliance identification numbers.....	64
Federal Communications Commission notice.....	64
FCC rating label.....	64
FCC Notice, Class A Equipment	64
FCC Notice, Class B Equipment	64

Declaration of conformity for products marked with the FCC logo, United States only.....	65
Modifications.....	65
Cables.....	65
Canadian notice (Avis Canadien).....	65
European Union regulatory notice	66
Disposal of waste equipment by users in private households in the European Union.....	66
Japanese notice	67
BSMI notice.....	67
Korean notice	67
Chinese notice	68
Vietnam compliance marking notice	68
Ukraine notice	68
Laser compliance	68
Battery replacement notice.....	69
Taiwan battery recycling notice.....	69
Acoustics statement for Germany (Geräuschemission)	69
Electrostatic discharge	71
Preventing electrostatic discharge	71
Grounding methods to prevent electrostatic discharge.....	71
Specifications	72
Environmental specifications	72
Server blade specifications	72
Support and other resources	73
Before you contact HP.....	73
HP contact information.....	73
Customer Self Repair	73
Acronyms and abbreviations.....	81
Documentation feedback	83
Index.....	84

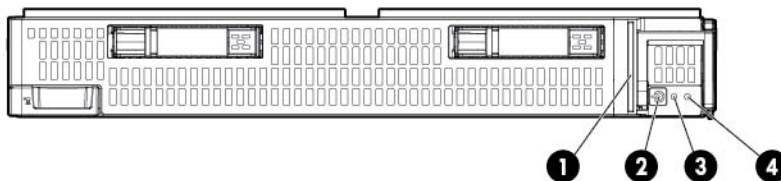
Component identification

Front panel components



Item	Description
1	HP c-Class Blade SUV cable connector (behind the serial label pull tab)
2	Serial label pull tab
3	Drive bay 1
4	Drive bay 2
5	Server blade release lever
6	Server blade release button

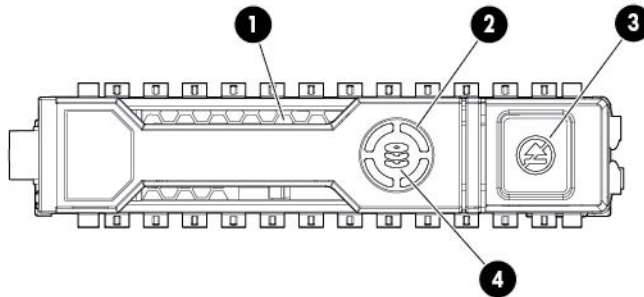
Front panel LEDs and buttons



Item	Description	Status
1	Health status LED bar	Solid Green = Normal (System is powered on.) Flashing Green = Power On/Standby Button service is being initialized. Flashing Amber = Degraded condition Flashing Red = Critical condition Off = Normal (System is in standby.)
2	Power On/Standby button and system power LED	Solid Green = System is powered on. Flashing Green = System is waiting to power on; Power On/Standby button is pressed. Solid Amber = System is in standby; Power On/Standby Button service is initialized. Off and the Health Status LED bar is off = The system has no power. Off and the Health Status LED bar is flashing green = The Power On/Standby Button service is being initialized.
3	UID LED	Solid Blue = Identified Flashing Blue = Active remote management Off = No active remote management

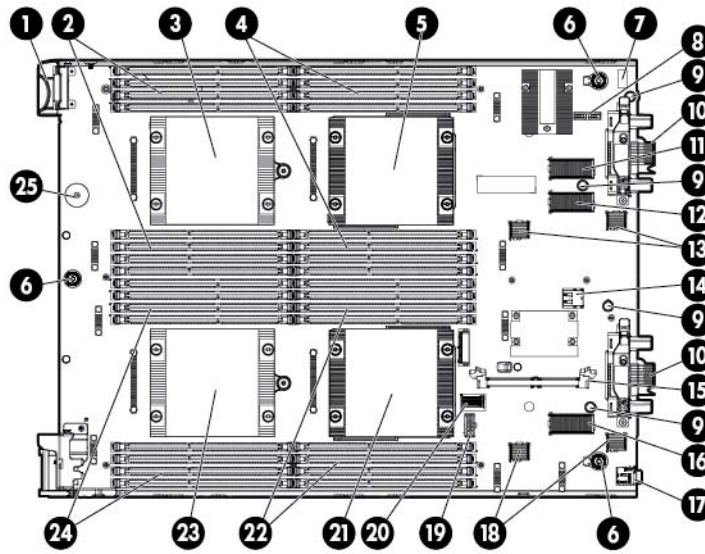
Item	Description	Status
4	FlexibleLOM LED	Green = Network linked Flashing Green = Network activity Off = No link or activity

Drive LED definitions



Item	LED	Status	Definition
1	Locate	Solid blue	The drive is being identified by a host application.
		Flashing blue	The drive carrier firmware is being updated or requires an update.
2	Activity ring	Rotating green	Drive activity
		Off	No drive activity
3	Do not remove	Solid white	Do not remove the drive. Removing the drive causes one or more of the logical drives to fail.
		Off	Removing the drive does not cause a logical drive to fail.
4	Drive status	Solid green	The drive is a member of one or more logical drives.
		Flashing green	The drive is rebuilding or performing a RAID migration, stripe size migration, capacity expansion, or logical drive extension, or is erasing.
		Flashing amber/green	The drive is a member of one or more logical drives and predicts the drive will fail.
		Flashing amber	The drive is not configured and predicts the drive will fail.
		Solid amber	The drive has failed.
		Off	The drive is not configured by a RAID controller.

System board components



Item	Description
1	HP c-Class Blade SUV cable connector
2	Processor 3 DIMM slots (8)
3	Processor socket 3 (populated)
4	Processor 1 DIMM slots (8)
5	Processor socket 1 (populated)
6	System board thumbscrew
7	System maintenance switch
8	TPM connector
9	Mezzanine assembly guide pins
10	Enclosure connector
11	Mezzanine connector 1 (Type A mezzanine only) ■
12	Mezzanine connector 2 (Type A or Type B mezzanine) ● ◆
13	FlexibleLOM 2 connectors (2) ◆
14	Internal USB connector
15	Cache module connector
16	Mezzanine connector 3 (Type A or Type B mezzanine) ● ◆
17	MicroSD card slot
18	FlexibleLOM 1 connectors (2) ◆
19	Drive power connector
20	Drive signal connector
21	Processor socket 2 (populated)
22	Processor 2 DIMM slots (8)
23	Processor socket 4 (populated)
24	Processor 4 DIMM slots (8)
25	System battery

The symbols ◆ ■ ● ◆ correspond to the symbols located on the interconnect bays. For more information, see the *HP ProLiant BL660c Gen8 Server Blade Installation Instructions* on the HP website (<http://www.hp.com/support>).

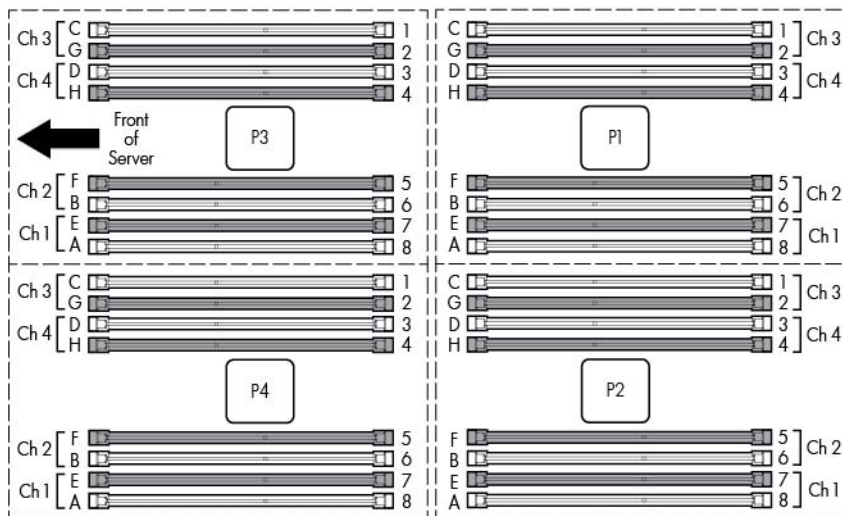
Mezzanine connector definitions

A PCIe x8 mezzanine connector supports x16 cards at up to x8 speeds.

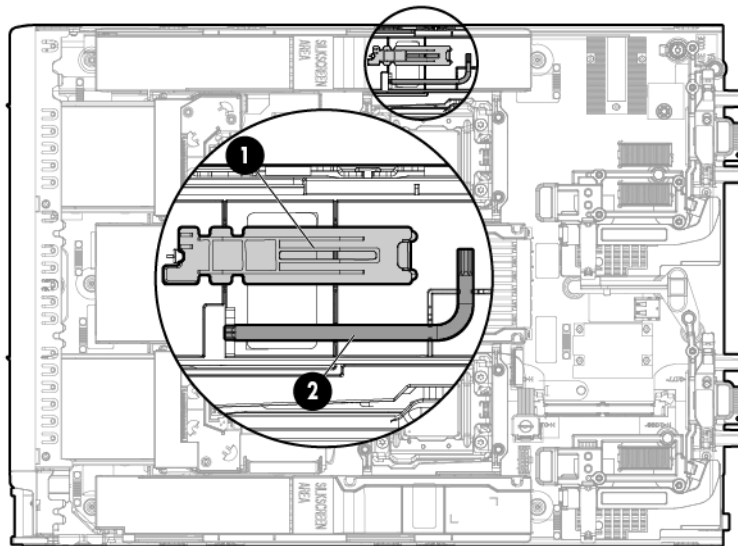
Item	PCIe
Mezzanine connector 1	x8, Type A mezzanine card only
Mezzanine connector 2	x16, Type A or B mezzanine card
Mezzanine connector 3	x16, Type A or B mezzanine card

DIMM slot locations

DIMM slots are numbered sequentially (1 through 8) for each processor. The supported AMP modes use the alpha assignments for population order and the slot numbers designate the DIMM slot ID for spare replacement.

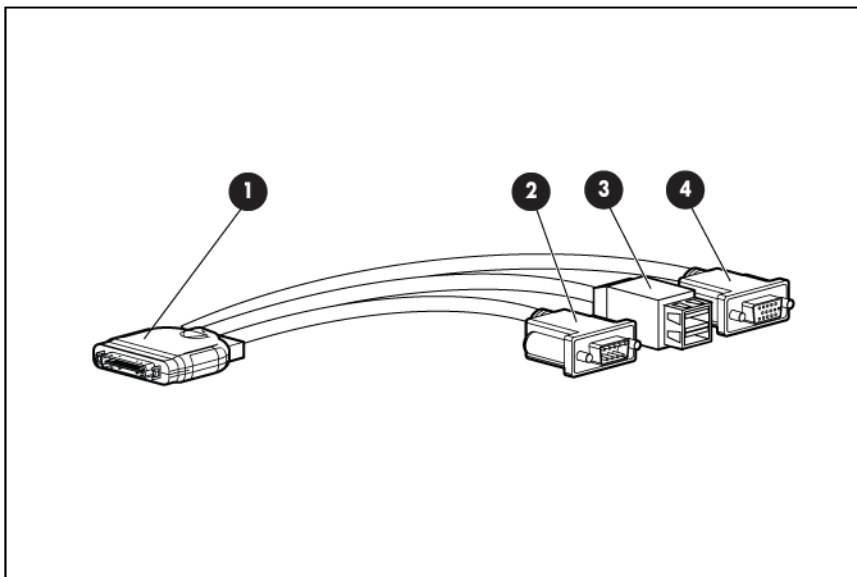


Tool locations



Item	Description
1	DIMM tool
2	T-15 Torx screwdriver

HP c-Class Blade SUV Cable



Item	Connector	Description
1	Server blade	For connecting to the SUV connector on the server blade front panel
2	Video	For connecting a video monitor
3	USB	For connecting up to two USB devices

Item	Connector	Description
4	Serial	For trained personnel to connect a null modem serial cable and perform advanced diagnostic procedures

Operations

Power up the server blade

The Onboard Administrator initiates an automatic power-up sequence when the server blade is installed. If the default setting is changed, use one of the following methods to power up the server blade:

- Use a virtual power button selection through iLO.
- Press and release the Power On/Standby button.

When the server blade goes from the standby mode to the full power mode, the system power LED changes from amber to solid green. The health status LED bar flashes green when the Power On/Standby Button service is being initialized. For more information about the system power LED status, see "Front panel LEDs ("Front panel LEDs and buttons" on page 6)."

For more information about the Onboard Administrator, see the enclosure setup and installation guide on the HP website (<http://www.hp.com/support/oa>).

For more information about iLO, see "HP iLO (on page 50)."

Power down the server blade

Before powering down the server blade for any upgrade or maintenance procedures, perform a backup of critical server data and programs.



IMPORTANT: When the server blade is in standby mode, auxiliary power is still being provided to the system.

Depending on the Onboard Administrator configuration, use one of the following methods to power down the server blade:

- Press and release the Power On/Standby button.
This method initiates a controlled shutdown of applications and the OS before the server blade enters standby mode.
- Press and hold the Power On/Standby button for more than 4 seconds to force the server blade to enter standby mode.
This method forces the server blade to enter standby mode without properly exiting applications and the OS. If an application stops responding, you can use this method to force a shutdown.
- Use a virtual power button selection through iLO.
This method initiates a controlled remote shutdown of applications and the OS before the server blade enters standby mode.
- Use the Onboard Administrator CLI to execute one of the following commands:
 - `poweroff server [bay number]`
This command initiates a controlled shutdown of applications and the OS before the server blade enters standby mode.

- `poweroff server [bay number] force`

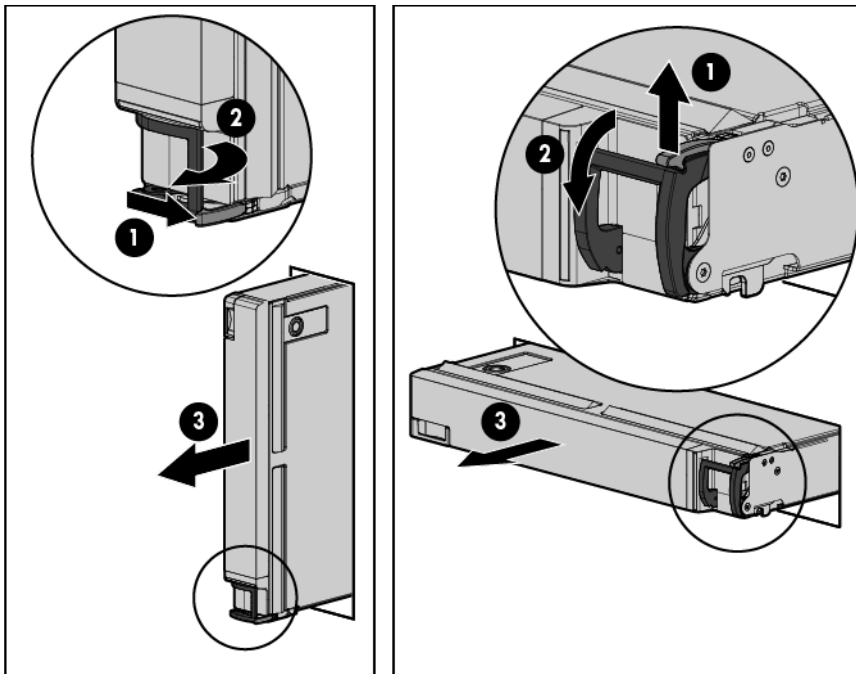
This form of the command forces the server blade to enter standby mode without properly exiting applications and the OS. If an application stops responding, this method forces a shutdown.

- Use the Onboard Administrator GUI to initiate a shutdown:
 - a. Select the **Enclosure Information** tab.
 - b. In the Device Bays item, select the **Overall** checkbox.
 - c. From the Virtual Power menu, initiate a shutdown of applications and the OS:
 - For a controlled shutdown, select **Momentary Press**.
 - For an emergency shutdown, select **Press and Hold**.

Before proceeding, verify the server blade is in standby mode by observing that the system power LED is amber.

Remove the server blade

1. Identify the proper server blade.
2. Power down the server blade (on page 12).
3. Remove the server blade.



4. Place the server blade on a flat, level work surface.

WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

CAUTION: To prevent damage to electrical components, properly ground the server blade before beginning any installation procedure. Improper grounding can cause ESD.

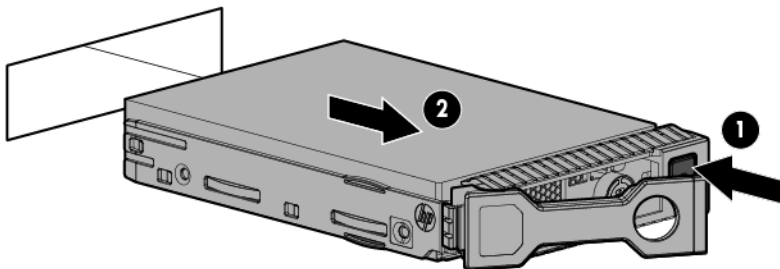
Remove the access panel

To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Press the access panel release button.
4. Slide the access panel towards the rear of the server blade, and then lift to remove the panel.

Remove a drive

1. Back up all server blade data on the drive.
2. Remove the drive.



Removing DIMM baffles

CAUTION: To avoid damage to the server blade and the enclosure, install all DIMM baffles in the proper location after adding or replacing DIMMs. DIMM baffles that are missing or installed incorrectly can compromise server blade and enclosure cooling.

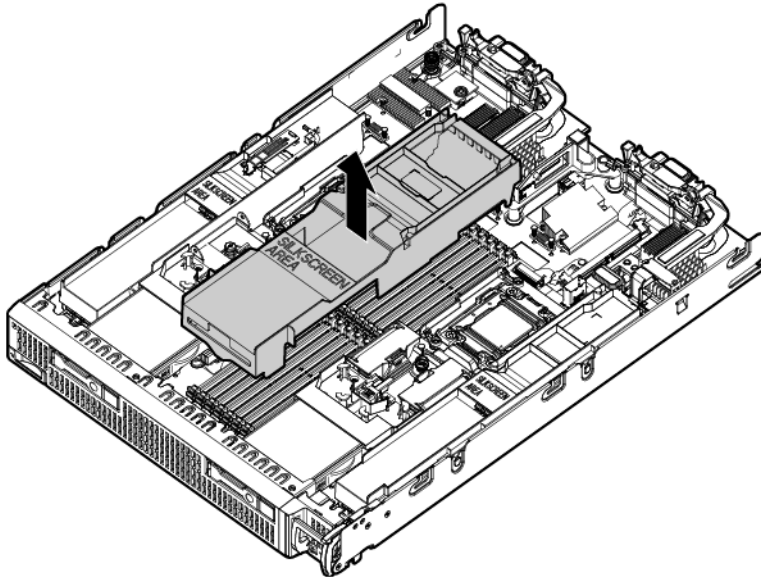
The server blade contains three DIMM baffles.

Remove the center DIMM baffle

To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Disconnect any cables that may be routed across the DIMM baffle.

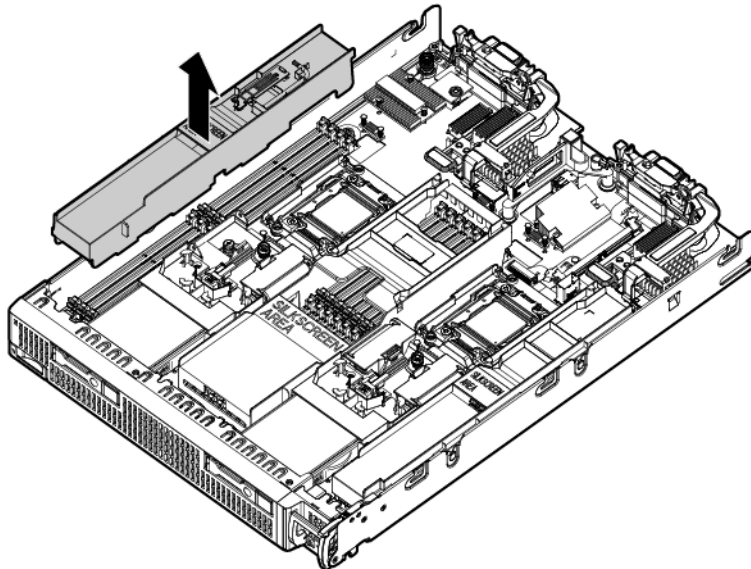
5. Remove the center DIMM baffle.



Remove the left DIMM baffle

To remove the component:

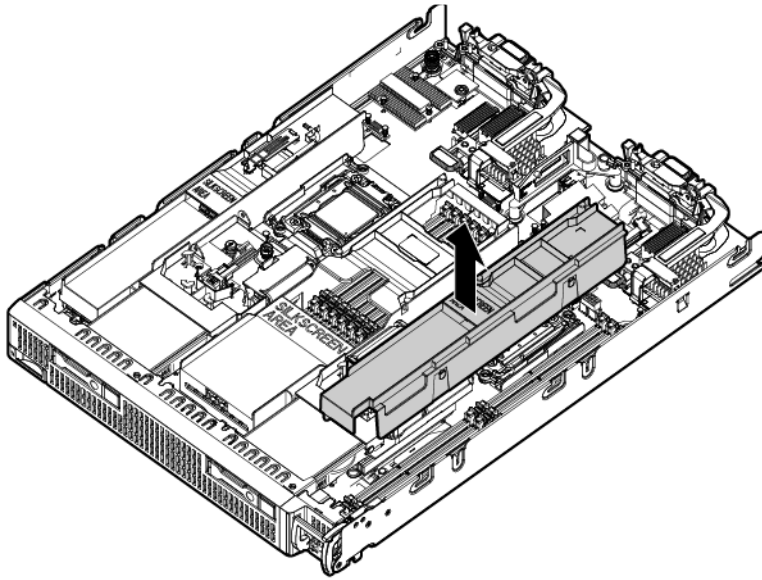
1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Disconnect any cables that may be routed across the DIMM baffle.
5. Remove the left DIMM baffle.



Remove the right DIMM baffle

To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Disconnect any cables that may be routed across the DIMM baffle.
5. Remove the right DIMM baffle.

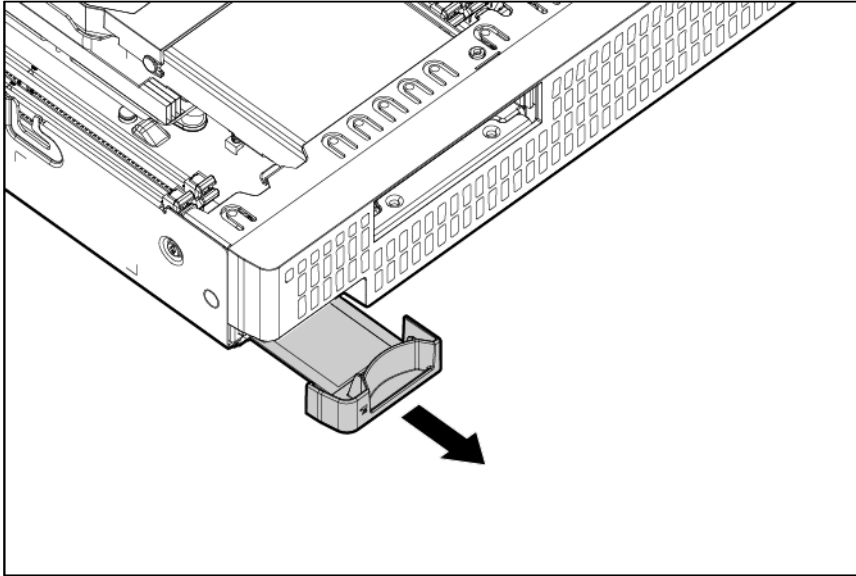


Remove the front panel/drive cage assembly

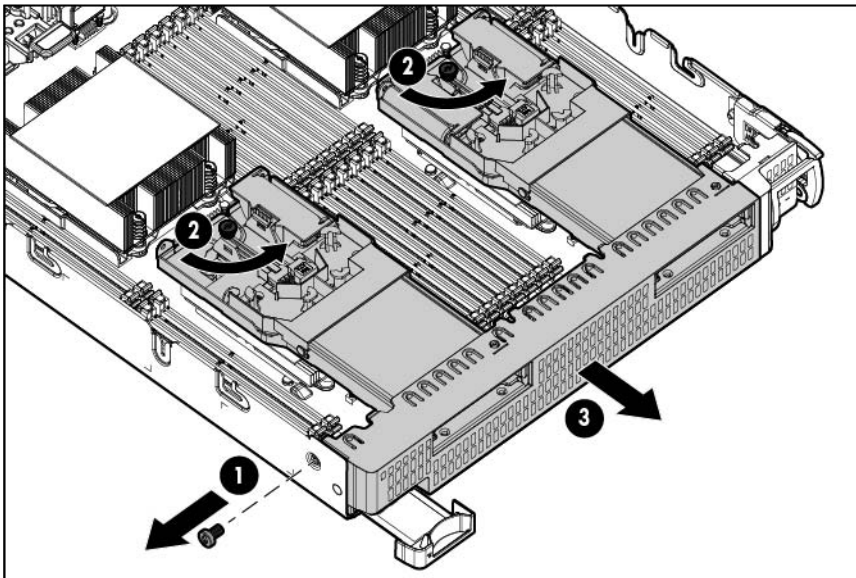
To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Remove all drives ("[Remove a drive](#)" on page 14).
5. Remove all DIMM baffles ("[Removing DIMM baffles](#)" on page 14).
6. Remove all FBWC capacitor packs ("[FBWC capacitor pack options](#)" on page 39).
7. Disconnect the signal cable and the power cable from the SAS backplane.

8. Extend the serial label pull tab.



9. Remove the front panel/drive cage assembly.

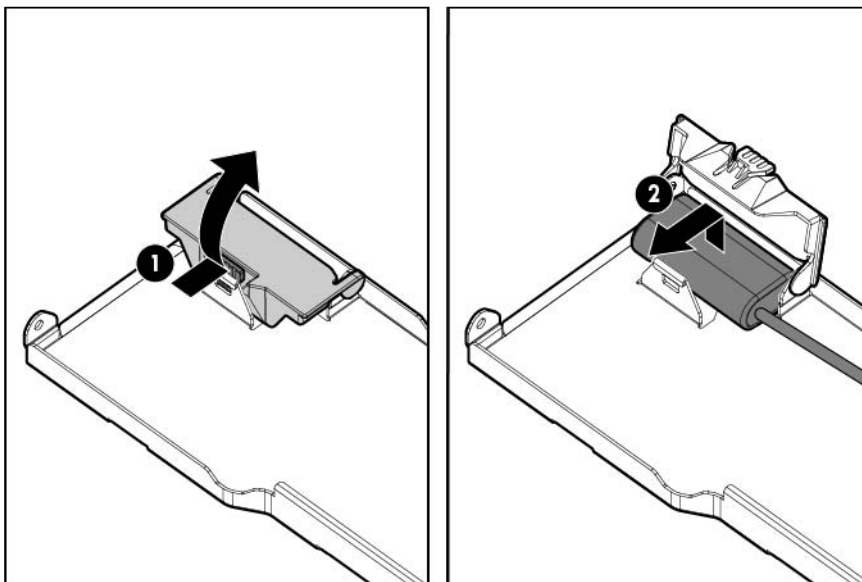


Remove the FBWC capacitor pack

To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Locate the capacitor pack on the drive cage. For more information, see "FBWC capacitor pack cabling (on page 46)."

5. Remove the capacitor pack from the carrier.



Setup

Installing an HP BladeSystem c-Class enclosure

Before performing any server blade-specific procedures, install an HP BladeSystem c-Class enclosure.

The most current documentation for server blades and other HP BladeSystem components is available at the HP website (<http://www.hp.com/go/bladepystem/documentation>).

Documentation is also available in the following locations:

- Documentation CD that ships with the enclosure
- HP website (<http://www.hp.com/go/bizsupport>)

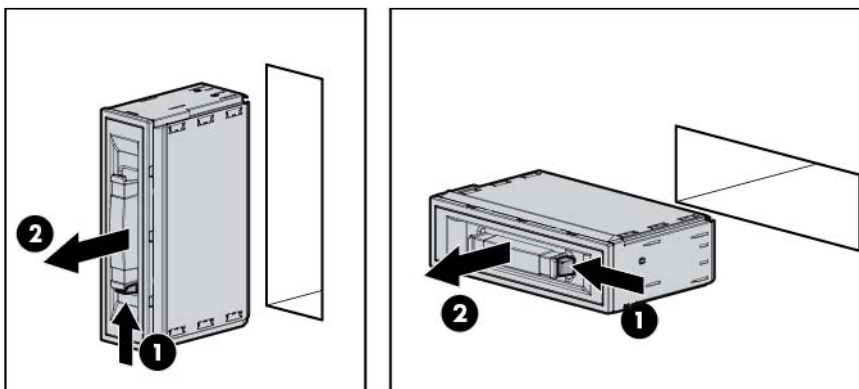
Preparing the enclosure

HP BladeSystem enclosures ship with device bay dividers to support half-height devices. To install a full-height device, remove the blanks and the corresponding device bay divider.

CAUTION: To prevent improper cooling and thermal damage, do not operate the server blade or the enclosure unless all drive and device bays are populated with either a component or a blank.

IMPORTANT: For optimal cooling and system performance, configure the c7000 enclosure with ten fans and configure the c3000 enclosure with six fans.

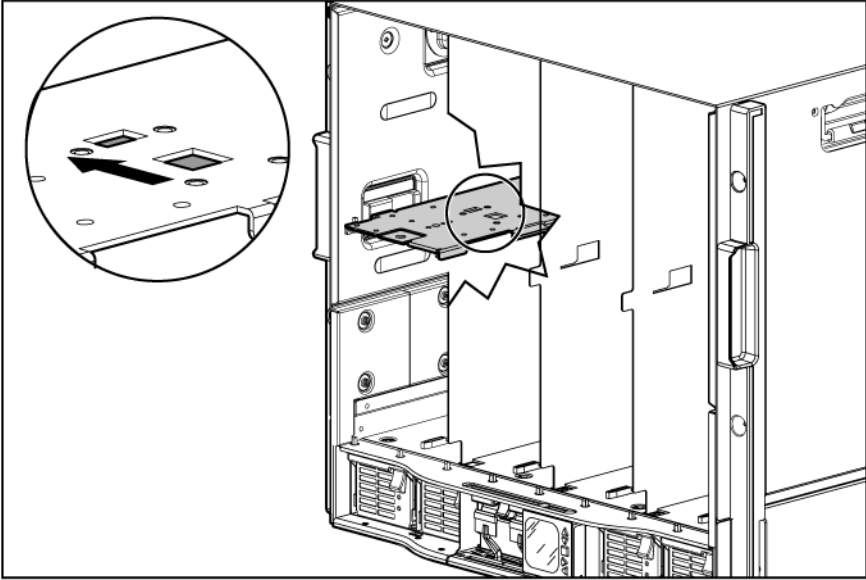
1. Remove the device bay blank.



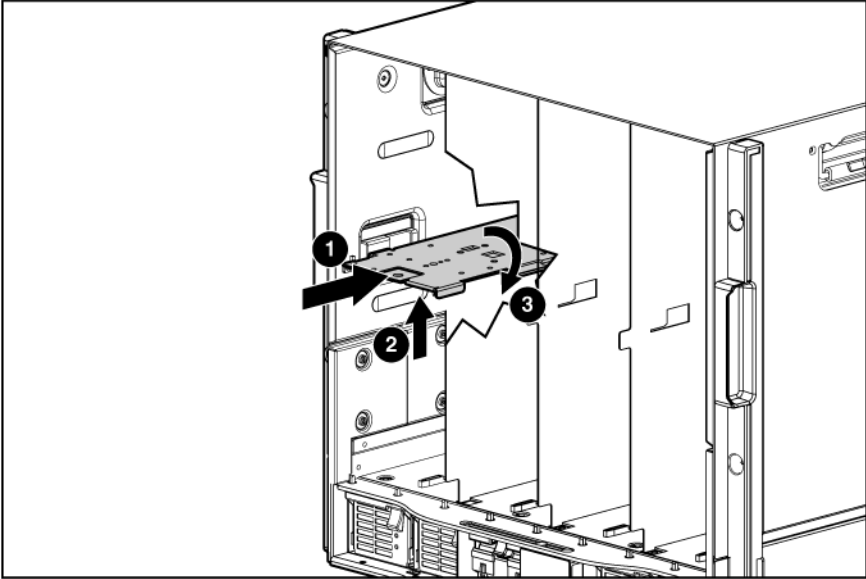
2. Remove the three adjacent blanks.

Removing a c7000 device bay divider

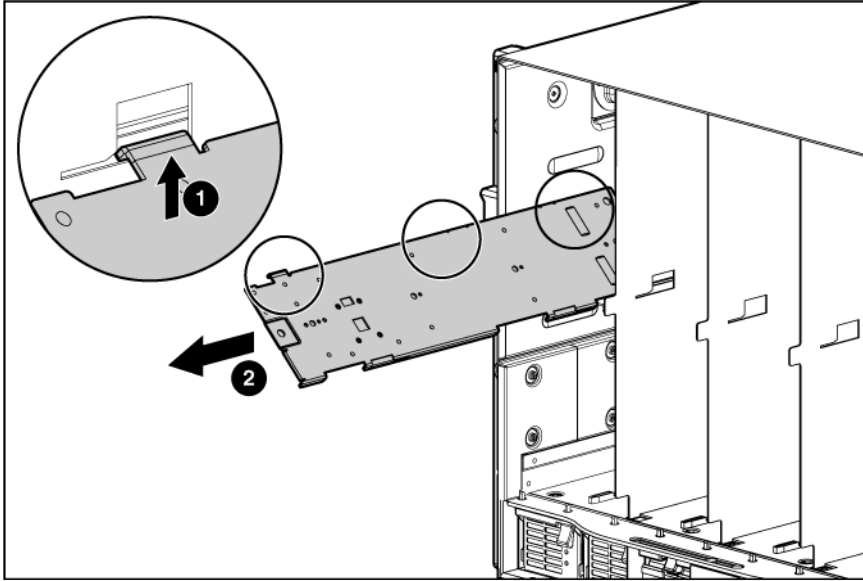
- 1. Slide the device bay shelf locking tab to the left to open it.



- 2. Push the device bay shelf back until it stops, lift the right side slightly to disengage the two tabs from the divider wall, and then rotate the right edge downward (clockwise).

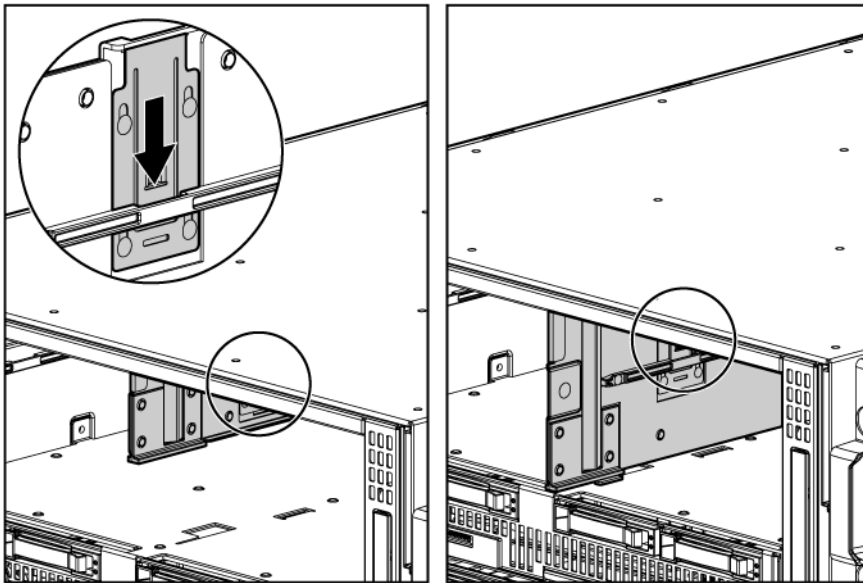


3. Lift the left side of the device bay shelf to disengage the three tabs from the divider wall, and then remove it from the enclosure.



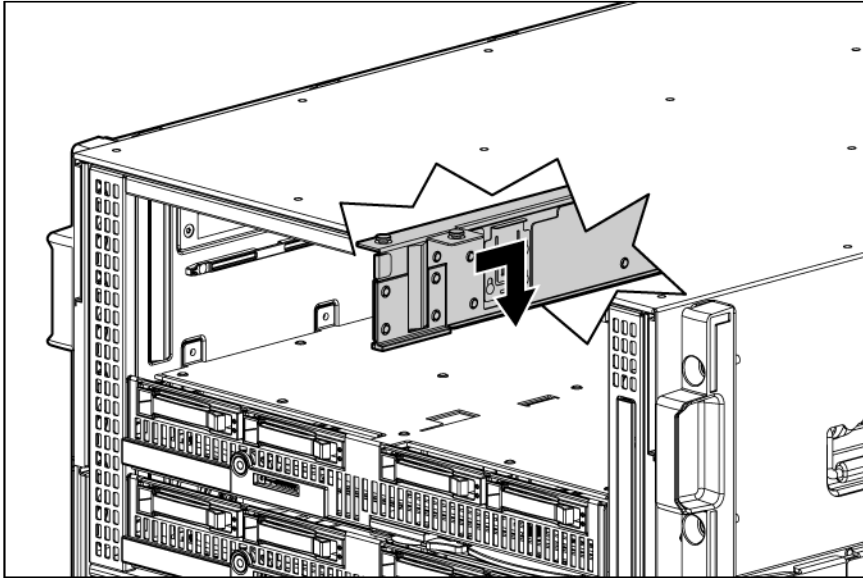
Removing a c3000 device bay mini-divider or device bay divider

1. Slide the locking tab down.

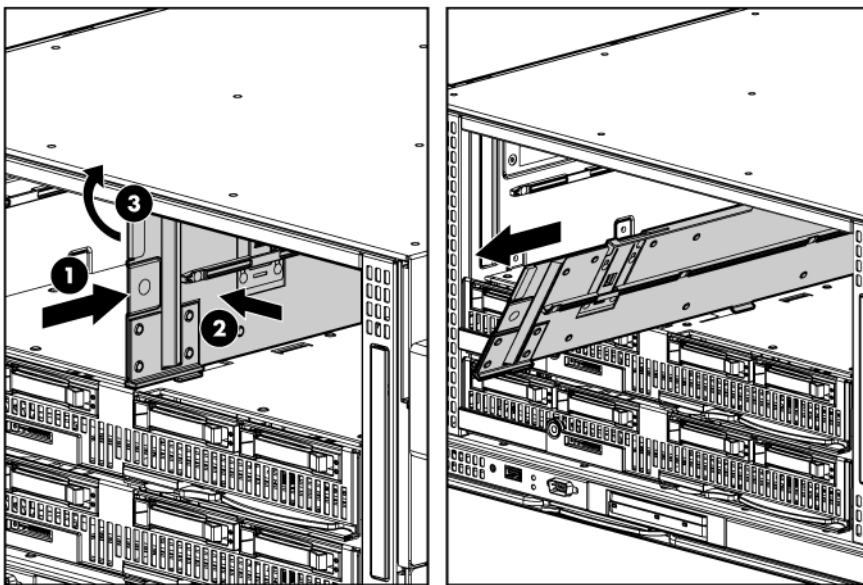


2. Remove the mini-divider or divider:
 - o c3000 mini-divider:

Push the divider toward the back of the enclosure until the divider drops out of the chassis.



- o c3000 divider:
 - a. Push the divider toward the back of the enclosure until it stops.
 - b. Slide the divider to the left to disengage the tabs from the wall.
 - c. Rotate the divider clockwise.
 - d. Remove the divider from the enclosure.

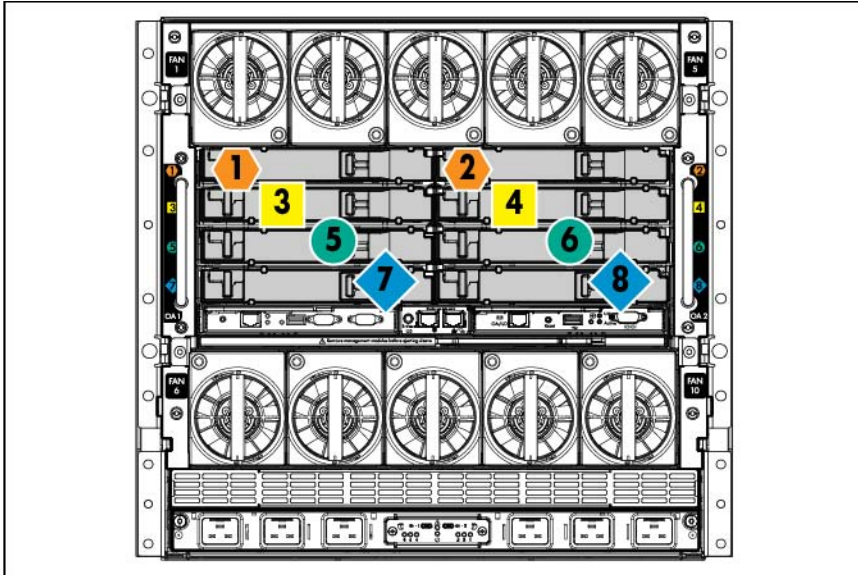


Installing interconnect modules

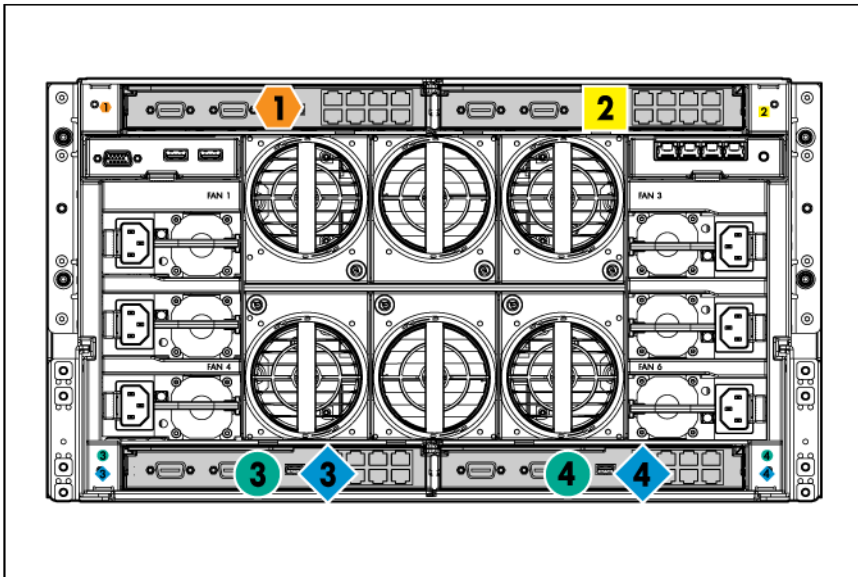
For specific steps to install interconnect modules, see the documentation that ships with the interconnect module.

Interconnect bay numbering and device mapping

- HP BladeSystem c7000 Enclosure



- HP BladeSystem c3000 Enclosure



To support network connections for specific signals, install an interconnect module in the bay corresponding to the embedded adapter or mezzanine signals.

Server blade signal	c7000 interconnect bay	c3000 interconnect bay	Interconnect bay labels
FlexibleLOM 1 (Embedded)	1	1	Orange diamond
FlexibleLOM 2 (Embedded)	2	1	Orange diamond
Mezzanine 1	3 and 4	2	Yellow square
Mezzanine 2	5 and 6*	3 and 4	Green circle
	7 and 8**	3 and 4	Blue diamond

Server blade signal	c7000 interconnect bay	c3000 interconnect bay	Interconnect bay labels
Mezzanine 3	5 and 6**	3 and 4	●
	7 and 8*	3 and 4	◆

* Dual port mezzanine card ports and four-port mezzanine card ports 1 and 2

** Four-port mezzanine card ports 3 and 4

For detailed port mapping information, see the HP BladeSystem enclosure installation poster or the HP BladeSystem enclosure setup and installation guide on the HP website (<http://www.hp.com/go/bladepystem/documentation>).

Connecting to the network

To connect the HP BladeSystem to a network, each enclosure must be configured with network interconnect devices to manage signals between the server blades and the external network.

Two types of interconnect modules are available for HP BladeSystem c-Class enclosures: Pass-Thru modules and switch modules. For more information about interconnect module options, see the HP website (<http://www.hp.com/go/bladepystem/interconnects>).



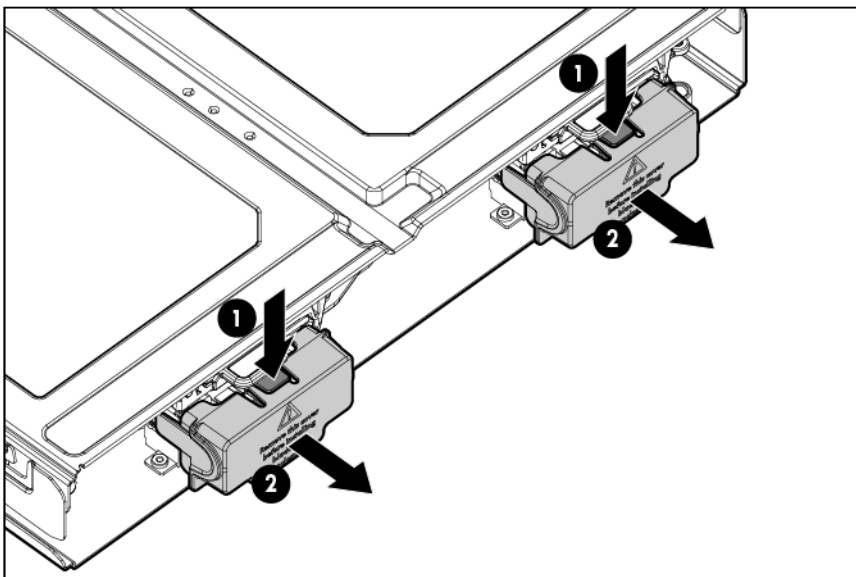
IMPORTANT: To connect to a network with a Pass-Thru module, always connect the Pass-Thru module to a network device that supports Gigabit or 10 Gb speed, depending on the corresponding Pass-Thru model.

Installing server blade options

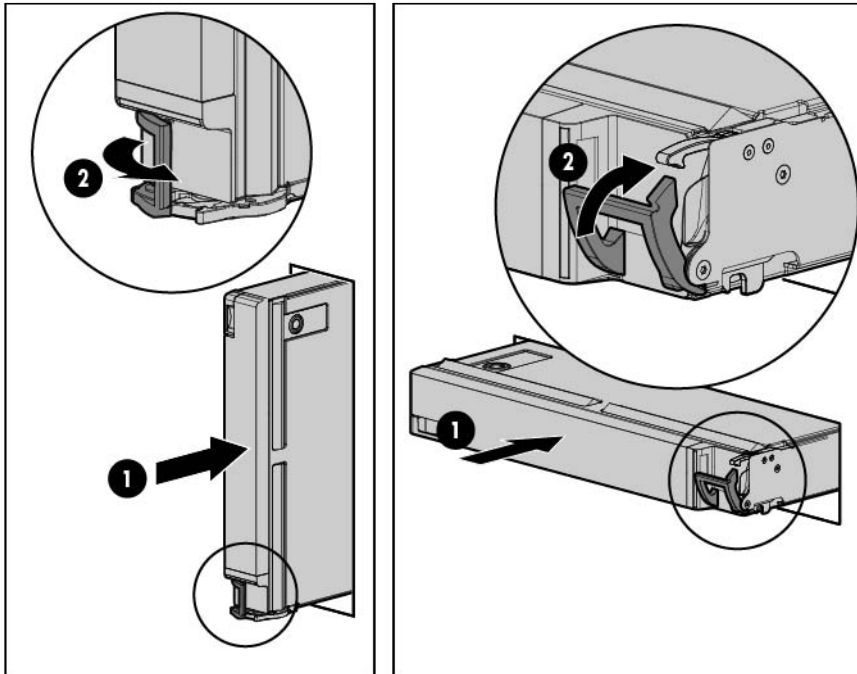
Before installing and initializing the server blade, install any server blade options, such as an additional processor, hard drive, or mezzanine card.

Installing a server blade

1. Remove the connector covers.



2. Install the server blade.

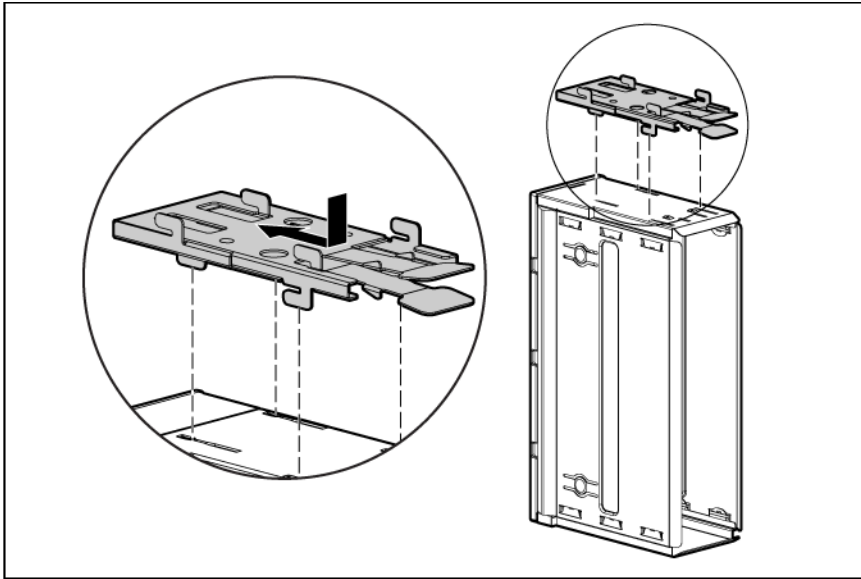


Assembling a full height blank

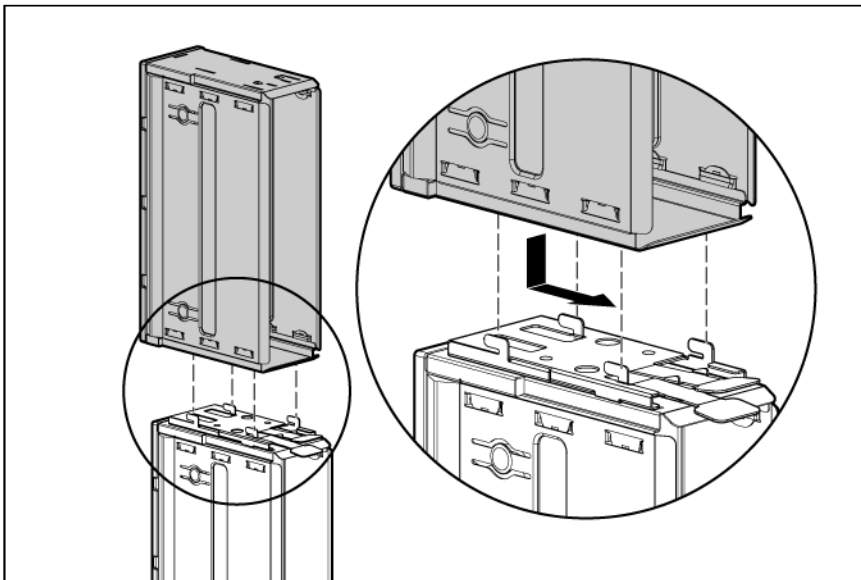
△ **CAUTION:** To prevent improper cooling and thermal damage, do not operate the server blade or the enclosure unless all drive and device bays are populated with either a component or a blank.

1. Obtain the coupler plate:
 - If you are using a device bay blank that came with the enclosure, the coupler plate can be found with the contents of the full-height device shipping box.
 - If you are using a device bay blank that you purchased as an option, remove the coupler plate from inside the blank.

2. Fit the coupler plate into the slots on top of the blank, and then slide the coupler plate back until it snaps into place.



3. Fit the slots on the bottom of the second blank on to the tabs on the coupler plate, and then slide the second blank forward until it snaps in place.



4. Install the full-height blank into the device bay.

Completing the configuration

To complete the server blade and HP BladeSystem configuration, see the overview card that ships with the enclosure.

Hardware options installation

Introduction

If more than one option is being installed, read the installation instructions for all the hardware options and identify similar steps to streamline the installation process.

⚠ WARNING: To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

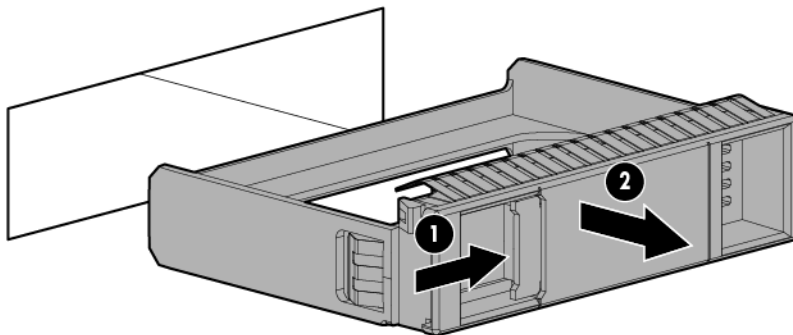
⚠ CAUTION: To prevent damage to electrical components, properly ground the server before beginning any installation procedure. Improper grounding can cause electrostatic discharge.

Drive option

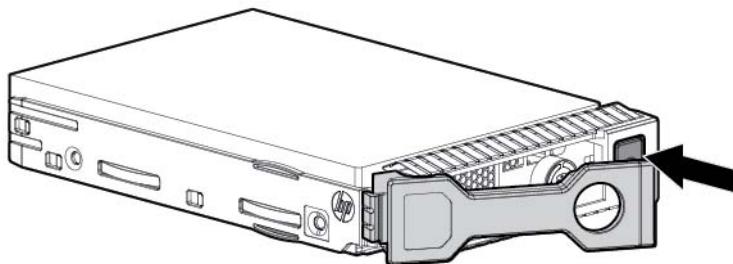
The server blade supports up to two SAS, SATA, or solid state drives.

⚠ CAUTION: To prevent improper cooling and thermal damage, do not operate the server blade or the enclosure unless all drive and device bays are populated with either a component or a blank.

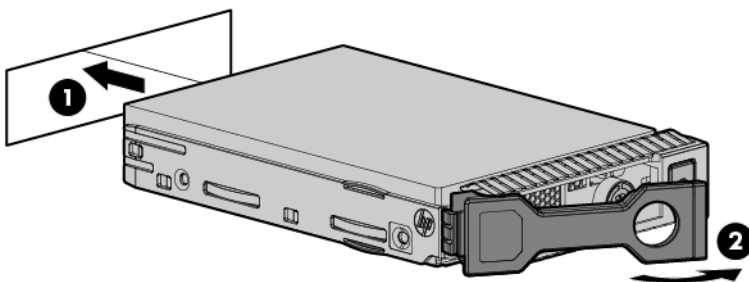
1. Remove the drive blank.



2. Prepare the drive.



3. Install the drive.



4. Determine the status of the drive from the drive LED definitions (on page 7).

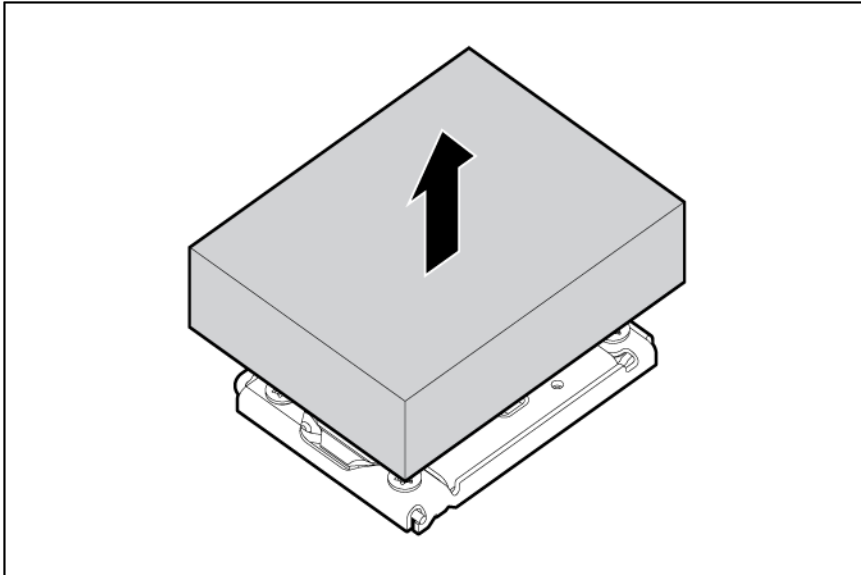
Processor option

- WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.
- CAUTION:** To prevent possible server blade malfunction and damage to the equipment, multiprocessor configurations must contain processors with the same part number.
- CAUTION:** The heatsink thermal interface media is not reusable and must be replaced if the heatsink is removed from the processor after it has been installed.
- CAUTION:** To prevent possible server blade overheating, always populate processor sockets with a processor and a heatsink or a heatsink blank.
- IMPORTANT:** Processor sockets 1 and 2 must always be populated. If either processor socket is empty, the server blade does not power up.

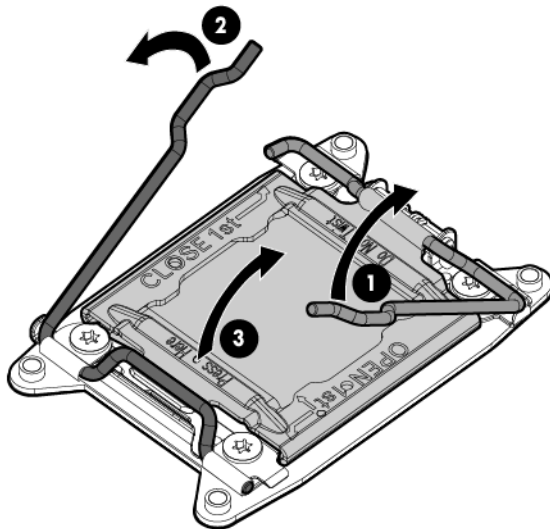
To install a processor:

1. Update the system ROM.
Locate and download the latest ROM version from the HP website (<http://www.hp.com/support>).
Follow the instructions on the website to update the system ROM.
2. Power down the server blade (on page 12).

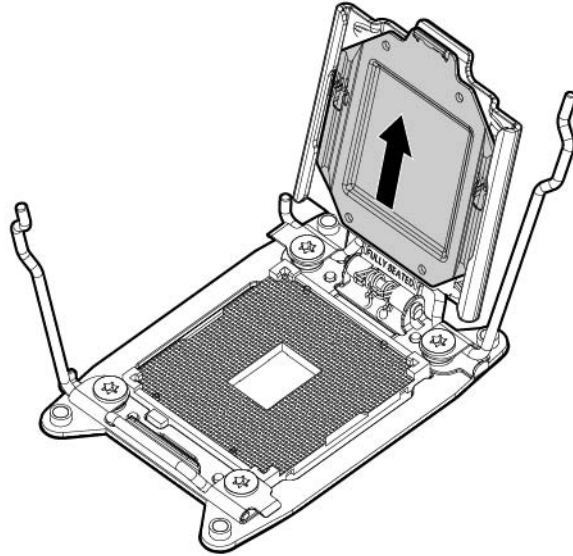
3. Remove the server blade (on page 13).
4. Remove the access panel (on page 14).
5. Remove all drives ("Remove a drive" on page 14).
6. Remove all DIMM baffles ("Removing DIMM baffles" on page 14).
7. Remove all FBWC capacitor packs ("FBWC capacitor pack options" on page 39).
8. Remove the front panel/drive cage assembly (on page 16).
9. Remove the heatsink blank. Retain the heatsink blank for future use.



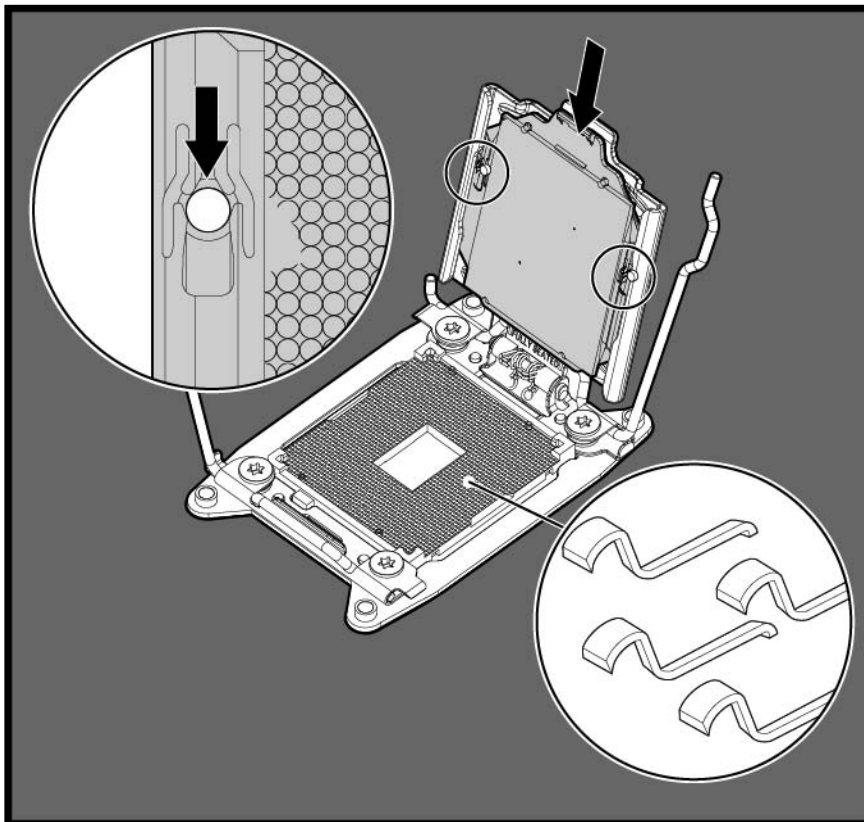
10. Open each of the processor locking levers in the order indicated, and then open the processor retaining bracket.



11. Remove the clear processor socket cover. Retain the processor socket cover for future use.



12. Install the processor. Verify that the processor is fully seated in the processor retaining bracket by visually inspecting the processor installation guides on either side of the processor. **THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED.**

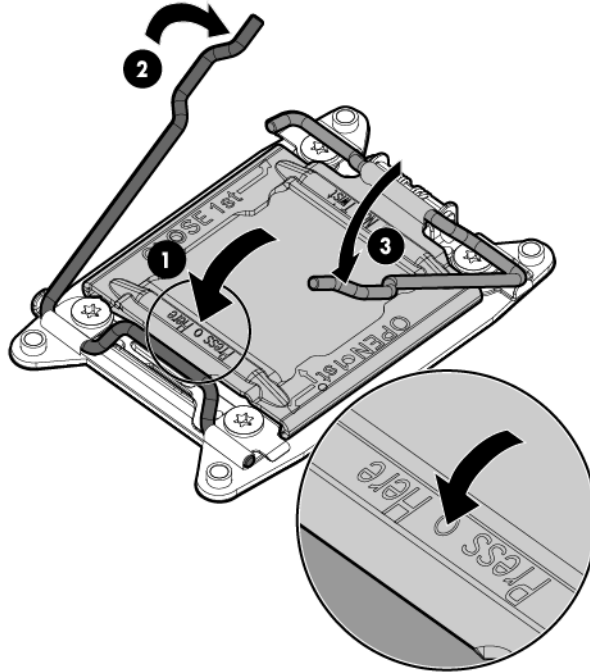


CAUTION: THE PINS ON THE SYSTEM BOARD ARE VERY FRAGILE AND EASILY DAMAGED. To avoid damage to the system board, do not touch the processor or the processor socket contacts.

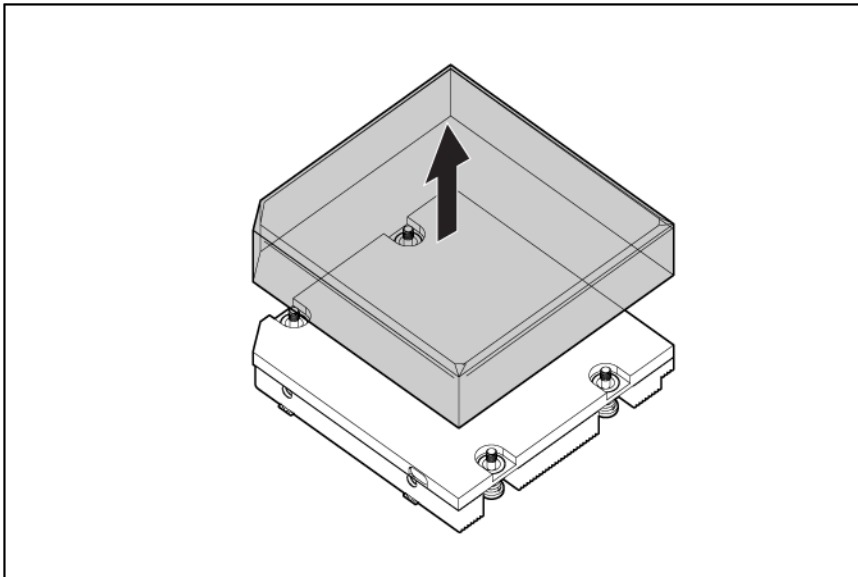
13. Close the processor retaining bracket. When the processor is installed properly inside the processor retaining bracket, the processor retaining bracket clears the flange on the front of the socket.

△ **CAUTION:** Do not press down on the processor. Pressing down on the processor may cause damage to the processor socket and the system board. Press only in the area indicated on the processor retaining bracket.

14. Press and hold the processor retaining bracket in place, and then close each processor locking lever. Press only in the area indicated on the processor retaining bracket.



15. Remove the thermal interface protective cover from the heatsink.

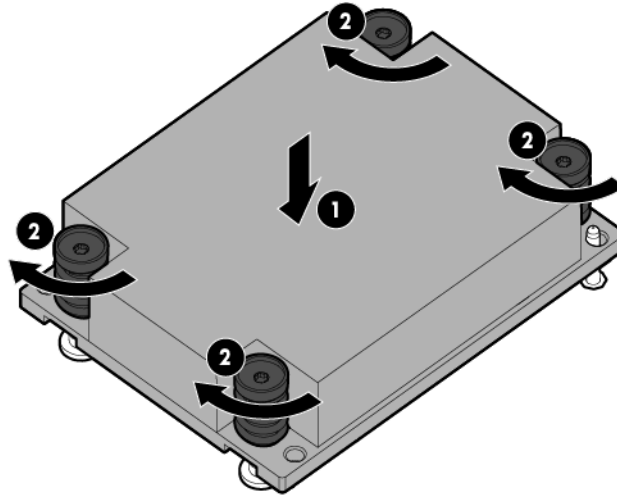


△ **CAUTION:** To avoid damage to the system board, processor socket, and screws, do not overtighten the heatsink screws. Use the wrench supplied with the system to reduce the possibility of overtightening the screws.



CAUTION: Heatsink retaining screws should be tightened in diagonally opposite pairs (in an "X" pattern).

16. Install the heatsink.



17. Install all DIMM baffles.
18. Install the front panel/drive cage assembly.
19. Install all FBWC capacitor packs ("[FBWC capacitor pack options](#)" on page 39).
20. Install all drives ("[Drive option](#)" on page 27).
21. Install the access panel.

Memory options



IMPORTANT: This server blade does not support mixing LRDIMMs or RDIMMs. Attempting to mix any combination of these DIMMs can cause the server to halt during BIOS initialization.

The memory subsystem in this server blade can support LRDIMMs or RDIMMs:

- RDIMMs offer lower latency in one DIMM per channel configurations and (relatively) low power consumption. They include address parity protection.
- LRDIMMs support higher densities than single- and dual-rank RDIMMs, and higher speeds than quad-rank RDIMMs. This support enables you to install more high capacity DIMMs, resulting in higher system capacities and higher bandwidth.

All types are referred to as DIMMs when the information applies to all types. When specified as LRDIMM or RDIMM, the information applies to that type only. All memory installed in the server blade must be the same type.

The server supports the following DIMM speeds:

- Single- and dual-rank PC3-10600 (DDR-1333) RDIMMs operating at up to 1333 MT/s
- Single- and dual-rank PC3-12800 (DDR-1600) RDIMMs operating at up to 1600 MT/s
- Quad-rank PC3L-10600 (DDR3-1333) LRDIMMs operating at up to 1333 MT/s

Speed, voltage, and capacity

DIMM type	DIMM rank	DIMM capacity	Native speed (MT/s)	Voltage
RDIMM	Single-rank	4 GB	1333	LV
RDIMM	Single-rank	4 GB	1600	STD
RDIMM	Single-rank	8 GB	1600	STD
RDIMM	Dual-rank	8 GB	1333	LV
RDIMM	Dual-rank	8 GB	1600	STD
RDIMM	Dual-rank	16 GB	1333	LV
RDIMM	Dual-rank	16 GB	1600	STD
LRDIMM	Quad-rank	32 GB	1333	LV

Memory operating data rate is dependent on processor capability, DIMM capability, operating voltage, and the number of DIMMs installed in a channel.

Populated DIMM speed (MT/s)

DIMM type	DIMM rank	1 DIMM per channel	2 DIMMs per channel
RDIMM (LV)	Single-rank (4 GB)	1333	1333
RDIMM (STD)	Single-rank (4 GB)	1600	1600
RDIMM (STD)	Single-rank (8 GB)	1600	1600
RDIMM (LV)	Dual-rank (8 GB)	1333	1333
RDIMM (STD)	Dual-rank (8 GB)	1600	1600
RDIMM (LV)	Dual-rank (16 GB)	1333	1333
RDIMM (STD)	Dual-rank (16 GB)	1600	1600
LRDIMM (LV)	Quad-rank (32 GB)	1333	1333

HP SmartMemory

HP SmartMemory, introduced for Gen8 servers, authenticates and unlocks certain features available only on HP Qualified memory and verifies whether installed memory has passed HP qualification and test processes. Qualified memory is performance-tuned for HP ProLiant and BladeSystem servers and provides future enhanced support through HP Active Health and manageability software.

Certain performance features are unique with HP SmartMemory. HP SmartMemory 1.35V DDR3-1333 Registered memory is engineered to achieve the same performance level as 1.5V memory. For example, while the industry supports DDR3-1333 RDIMM at 1.5V, this Gen8 server supports DDR3-1333 RDIMM at 1.35V. This difference equates to up to 20% less power at the DIMM level with no performance penalty.

Memory subsystem architecture

The memory subsystem in this server blade is divided into channels. Each processor supports four channels, and each channel supports two DIMM slots, as shown in the following table.

Channel	Slot	Slot number
1	A	1
	E	2
2	B	3
	F	4

Channel	Slot	Slot number
3	C	8
	G	7
4	D	6
	H	5

For the location of the slot numbers, see "DIMM slot locations (on page 9)."

This multi-channel architecture provides enhanced performance in Advanced ECC mode. This architecture also enables the Lockstep memory mode.

DIMM slots in this server are identified by number and by letter. Letters identify the population order. Slot numbers indicate the DIMM slot ID for spare replacement.

Single-, dual-, and quad-rank DIMMs

To understand and configure memory protection modes properly, an understanding of single-, dual-, and quad-rank DIMMs is helpful. Some DIMM configuration requirements are based on these classifications.

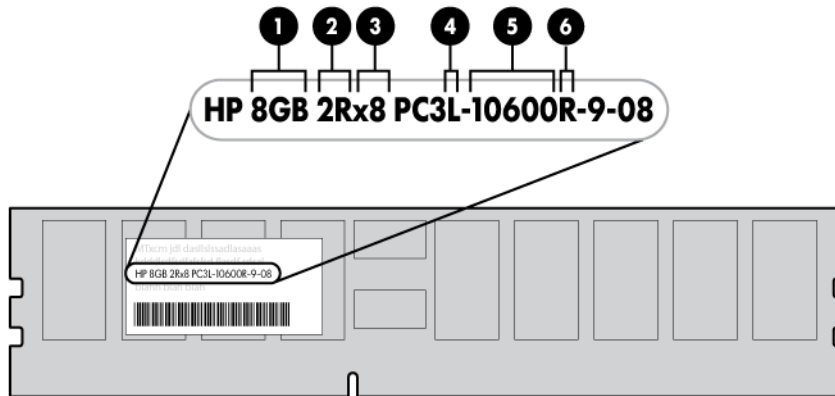
A single-rank DIMM has one set of memory chips that is accessed while writing to or reading from the memory. A dual-rank DIMM is similar to having two single-rank DIMMs on the same module, with only one rank accessible at a time. A quad-rank DIMM is, effectively, two dual-rank DIMMs on the same module. Only one rank is accessible at a time. The server blade memory control subsystem selects the proper rank within the DIMM when writing to or reading from the DIMM.

Dual- and quad-rank DIMMs provide the greatest capacity with the existing memory technology. For example, if current DRAM technology supports 8-GB single-rank DIMMs, a dual-rank DIMM would be 16 GB, and a quad-rank DIMM would be 32 GB.

LRDIMMs are labeled as quad-rank DIMMs. There are four ranks of DRAM on the DIMM, but the LRDIMM buffer creates an abstraction that allows the DIMM to appear as a dual-rank DIMM to the system. The LRDIMM buffer isolates the electrical loading of the DRAM from the system to allow for faster operation. This allows higher memory operating speed compared to quad-rank RDIMMs.

DIMM identification

To determine DIMM characteristics, use the label attached to the DIMM and the following illustration and table.



Item	Description	Definition
1	Size	—
2	Rank	1R = Single-rank 2R = Dual-rank 4R = Quad-rank
3	Data width	x4 = 4-bit x8 = 8-bit
4	Voltage rating	L = Low voltage (1.35v) U = Ultra low voltage (1.25v) Blank or omitted = Standard
5	Memory speed	12800 = 1600-MT/s 10600 = 1333-MT/s 8500 = 1066-MT/s
6	DIMM type	R = RDIMM (registered) E = UDIMM (unbuffered with ECC) L = LRDIMM (load reduced)

For the latest supported memory information, see the QuickSpecs on the HP website (<http://h18000.www1.hp.com/products/quickspecs/ProductBulletin.html>). At the website, choose the geographic region, and then locate the product by name or product category.

Memory configurations

To optimize server blade availability, the server blade supports the following AMP modes:

- Advanced ECC—provides up to 4-bit error correction and enhanced performance over Lockstep mode. This mode is the default option for this server blade.
- Online spare memory—provides protection against failing or degraded DIMMs. Certain memory is reserved as spare, and automatic failover to spare memory occurs when the system detects a DIMM that

is degrading. This allows DIMMs that have a higher probability of receiving an uncorrectable memory error (which would result in system downtime) to be removed from operation.

Advanced Memory Protection options are configured in RBSU. If the requested AMP mode is not supported by the installed DIMM configuration, the server blade boots in Advanced ECC mode. For more information, see "HP ROM-Based Setup Utility (on page 55)."

The server blade also can operate in independent channel mode or combined channel mode (lockstep). When running in lockstep mode, you gain reliability if running with RDIMMs (built with x4 DRAM devices). The system can survive the complete failure of two DRAM devices (DDDC). Running in independent mode, the server can only survive the complete failure of a single DRAM device (SDDC).

Maximum capacity

DIMM type	DIMM rank	Two processors	Four processors
RDIMM	Single-rank	128 GB	256 GB
RDIMM	Dual-rank	256 GB	512 GB
LRDIMM	Quad-rank	512 GB	1024 GB

For the latest memory configuration information, see the QuickSpecs on the HP website (<http://www.hp.com>).

Advanced ECC memory configuration

Advanced ECC memory is the default memory protection mode for this server blade. Standard ECC can correct single-bit memory errors and detect multi-bit memory errors. When multi-bit errors are detected using Standard ECC, the error is signaled to the server blade and causes the server blade to halt.

Advanced ECC protects the server blade against some multi-bit memory errors. Advanced ECC can correct both single-bit memory errors and 4-bit memory errors if all failed bits are on the same DRAM device on the DIMM.

Advanced ECC provides additional protection over Standard ECC because it is possible to correct certain memory errors that would otherwise be uncorrected and result in a server blade failure. Using HP Advanced Memory Error Detection technology, the server blade provides notification when a DIMM is degrading and has a higher probability of uncorrectable memory error.

Online Spare memory configuration

Online spare memory provides protection against degraded DIMMs by reducing the likelihood of uncorrected memory errors. This protection is available without any operating system support.

Online spare memory protection dedicates one rank of each memory channel for use as spare memory. The remaining ranks are available for OS and application use. If correctable memory errors occur at a rate higher than a specific threshold on any of the non-spare ranks, the server blade automatically copies the memory contents of the degraded rank to the online spare rank. The server blade then deactivates the failing rank and automatically switches over to the online spare rank.

Lockstep memory configuration

Lockstep mode provides protection against multi-bit memory errors that occur on the same DRAM device. Lockstep mode can correct any single DRAM device failure on x4 and x8 DIMM types. The DIMMs in each channel must have identical HP part numbers.

General DIMM slot population guidelines

Observe the following guidelines for all AMP modes:

- Install DIMMs only if the corresponding processor is installed.
- Balance the DIMMs across the installed processors.
- White DIMM slots denote the first slot of a channel (Ch 1-A, Ch 2-B, Ch 3-C, Ch 4-D).
- Do not mix RDIMMs and LRDIMMs.
- When two processors are installed, install the DIMMs in sequential alphabetic order balanced between the two processors: P1-A, P2-A, P1-B, P2-B, P1-C, P2-C, and so forth.
- When four processors are installed, install the DIMMs in sequential alphabetic order balanced across the four processors: P1-A, P2-A, P3-A, P4-A, P1-B, P2-B, P3-B, P4-B, P1-C, and so forth.
- For DIMM spare replacement, install the DIMMs per slot number as instructed by the system software.

For detailed memory configuration rules and guidelines, use the Online DDR3 Memory Configuration Tool on the HP website (<http://www.hp.com/go/ddr3memory-configurator>).

DIMM speeds are supported as indicated in the following table.

Populated slots (per channel)	Rank	Speeds supported (MT/s)
1, 2	Single- or dual-rank	1333, 1600
1, 2	Quad-rank	1333

Advanced ECC population guidelines

For Advanced ECC mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 37).
- DIMMs may be installed individually.

Online spare population

For Online Spare memory mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 37).
- Each channel must have a valid online spare configuration.
- Each channel can have a different valid online spare configuration.
- Each populated channel must have a spare rank:
 - A single dual-rank DIMM is not a valid configuration.
 - LRDIMMs are treated as dual-rank DIMMs.

Lockstep Memory population guidelines

For Lockstep memory mode configurations, observe the following guidelines:

- Observe the general DIMM slot population guidelines (on page 37).
- DIMM configuration on all channels of a processor must be identical.

- In multi-processor configurations, each processor must have a valid Lockstep Memory configuration.
- In multi-processor configurations, each processor may have a different valid Lockstep Memory configuration.

Population order

For memory configurations with a single processor or multiple processors, populate the DIMM slots in the following order:

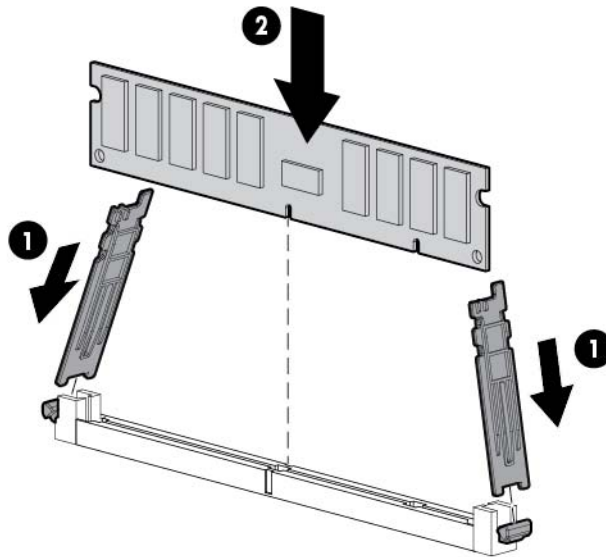
- LRDIMM: Sequentially in alphabetical order (A through H)
- RDIMM: Sequentially in alphabetical order (A through H)

After installing the DIMMs, use RBSU to configure Advanced ECC or online spare memory support.

Installing a DIMM

CAUTION: To avoid damage to the hard drives, memory, and other system components, the air baffle, drive blanks, and access panel must be installed when the server is powered up.

1. Power down the server ("[Power down the server blade](#)" on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Remove all DIMM baffles ("[Removing DIMM baffles](#)" on page 14).
5. Locate the DIMM tool ("[Tool locations](#)" on page 10) and remove it from the DIMM baffle.
6. Use the DIMM tool to open the DIMM slot.
7. Install the DIMM.



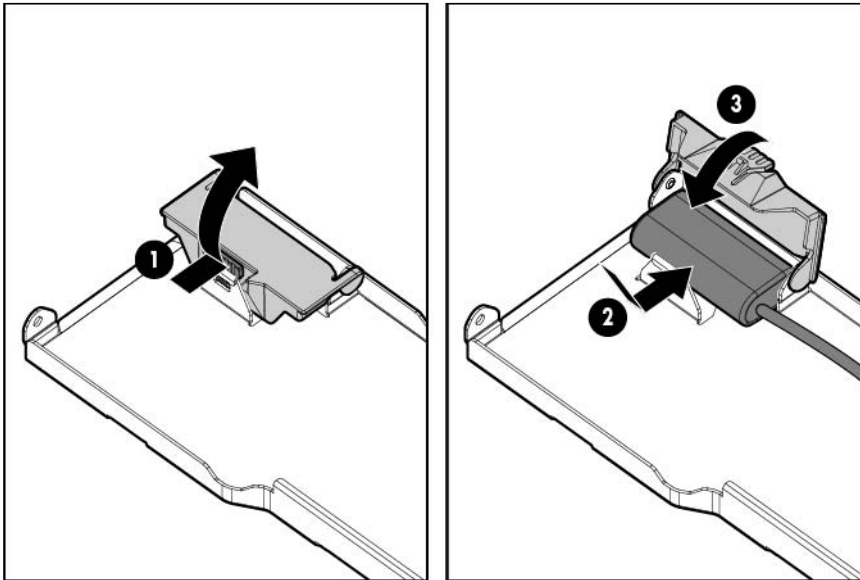
8. Install all DIMM baffles.
9. Install the access panel.

To configure the memory mode, use RBSU ("[HP ROM-Based Setup Utility](#)" on page 55).

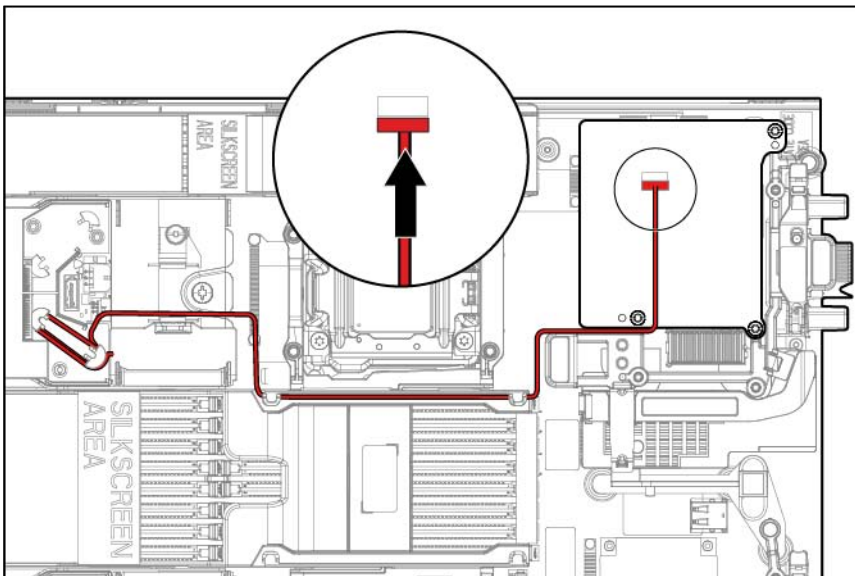
FBWC capacitor pack options

To install the component:

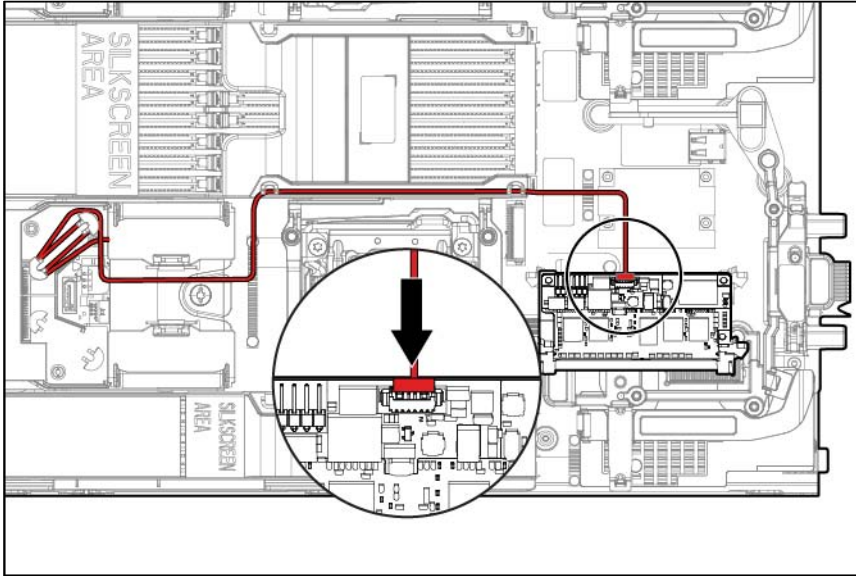
1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Install the FBWC capacitor pack in one of the three capacitor pack carriers.



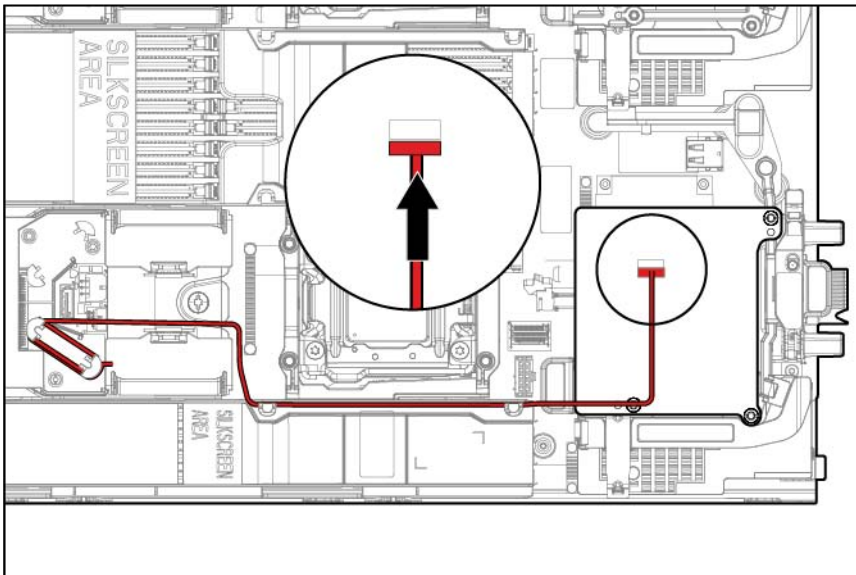
5. Route the FBWC capacitor pack cable. The DIMM baffles may be removed to route the cables, if necessary.
 - o Routing and connecting the FBWC capacitor pack cable to the mezzanine 1 or mezzanine 2 connector option



- Routing and connecting the FBWC capacitor pack cable to the cache module option



- Routing and connecting the FBWC capacitor pack cable to the mezzanine 3 connector option



6. Install the access panel.

Mezzanine card option

Optional mezzanine cards are classified as Type A mezzanine cards and Type B mezzanine cards. The type of the mezzanine card determines where it can be installed in the server blade.

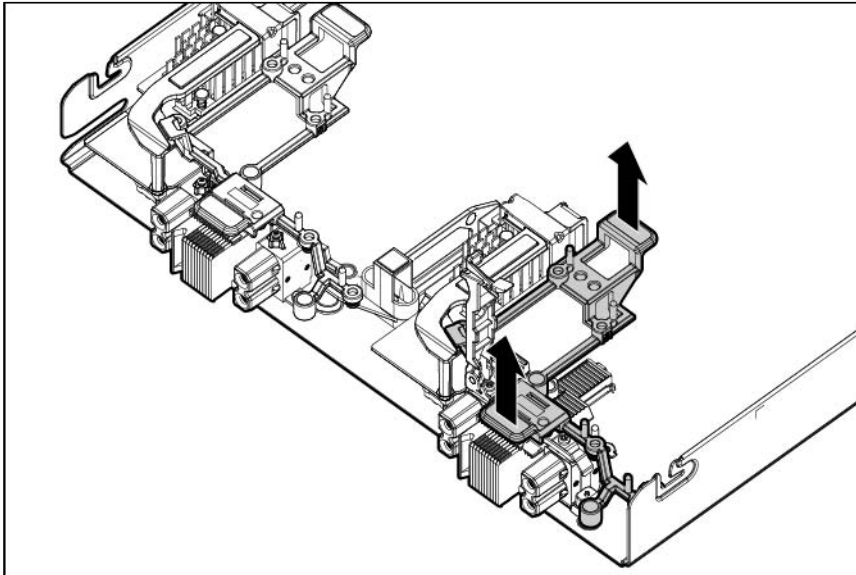
- Install Type A mezzanine cards on Mezzanine 1 connector, Mezzanine 2 connector, or Mezzanine 3 connector.
- Install Type B mezzanine cards on either Mezzanine 2 connector or Mezzanine 3 connector.

Optional mezzanine cards enable network connectivity or provide Fibre Channel support. For mezzanine card locations, see the system board components (on page 8).

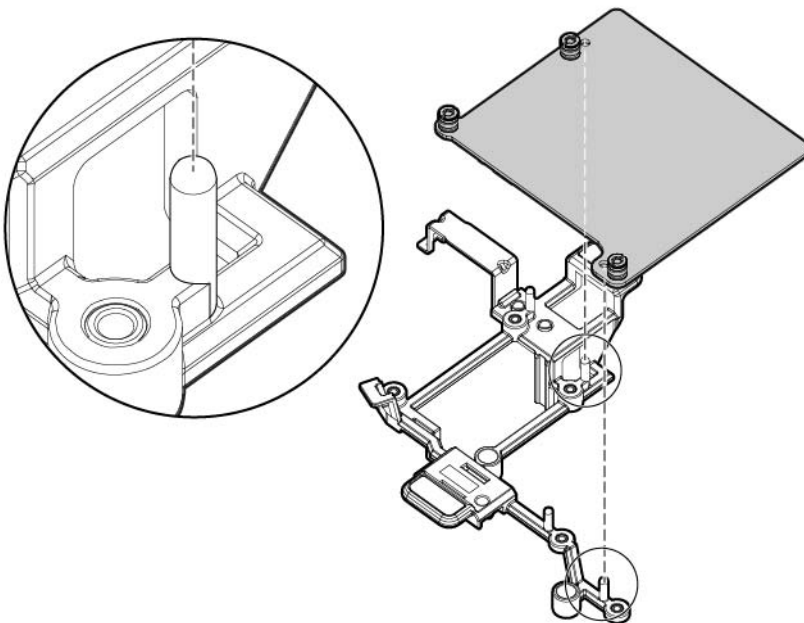
For mezzanine card mapping, see the *HP ProLiant BL660c Gen8 Server Blade Installation Instructions* or see "Interconnect bay numbering and device mapping (on page 23)."

To install the component:

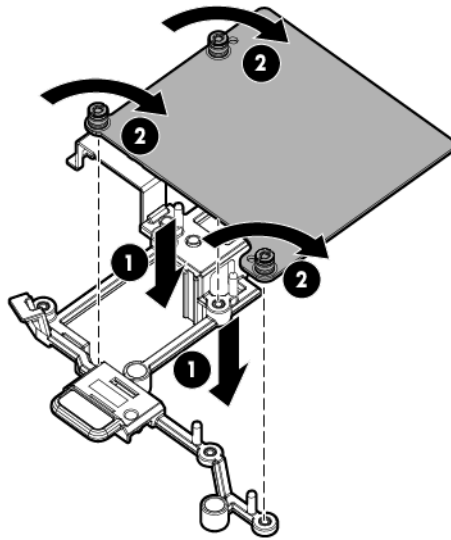
1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Remove the access panel (on page 14).
4. Remove the mezzanine assembly from the server blade.



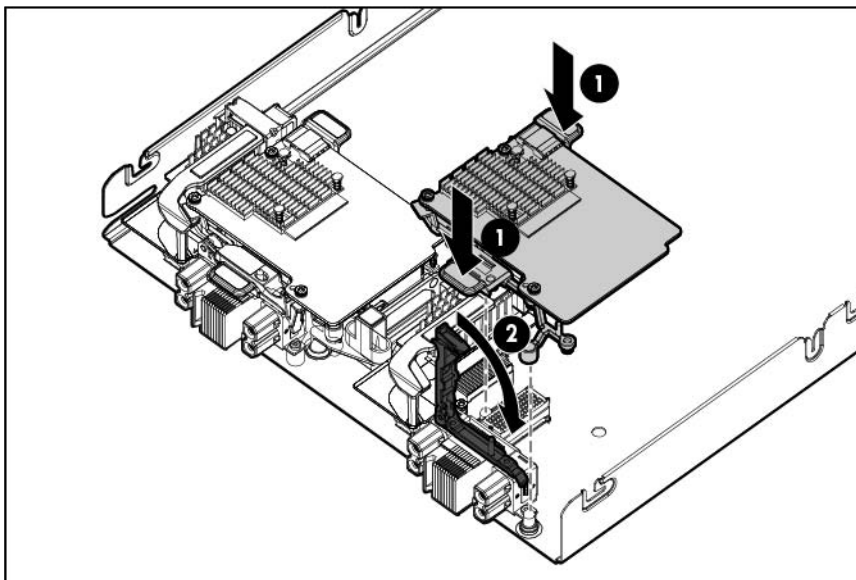
5. Align the mezzanine card with the guide pins on the mezzanine assembly.



6. Install the mezzanine card in the mezzanine assembly, and then tighten the mezzanine card screws to secure the card to the mezzanine assembly.



7. Align the mezzanine assembly with the guide pins on the system board, and then install the mezzanine assembly on the system board.
8. Press down firmly on the mezzanine assembly handles, and then close the mezzanine assembly latch.



9. Install the access panel.
10. Install the server blade ("Installing a server blade" on page 24).

HP Trusted Platform Module option


Use these instructions to install and enable a TPM on a supported server blade. This procedure includes three sections:

1. Installing the Trusted Platform Module board (on page 43).
2. Retaining the recovery key/password (on page 44).

3. Enabling the Trusted Platform Module (on page 45).

Enabling the TPM requires accessing RBSU ("HP ROM-Based Setup Utility" on page 55). For more information about RBSU, see the HP website (<http://www.hp.com/go/ilomgmtengine/docs>).


TPM installation requires the use of drive encryption technology, such as the Microsoft Windows BitLocker Drive Encryption feature. For more information on BitLocker, see the Microsoft website (<http://www.microsoft.com>).

 **CAUTION:** Always observe the guidelines in this document. Failure to follow these guidelines can cause hardware damage or halt data access.


When installing or replacing a TPM, observe the following guidelines:

- Do not remove an installed TPM. Once installed, the TPM becomes a permanent part of the system board.
- When installing or replacing hardware, HP service providers cannot enable the TPM or the encryption technology. For security reasons, only the customer can enable these features.
- When returning a system board for service replacement, do not remove the TPM from the system board. When requested, HP Service provides a TPM with the spare system board.
- Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.
- When using BitLocker, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker detects a possible compromise of system integrity.
- HP is not liable for blocked data access caused by improper TPM use. For operating instructions, see the encryption technology feature documentation provided by the operating system.

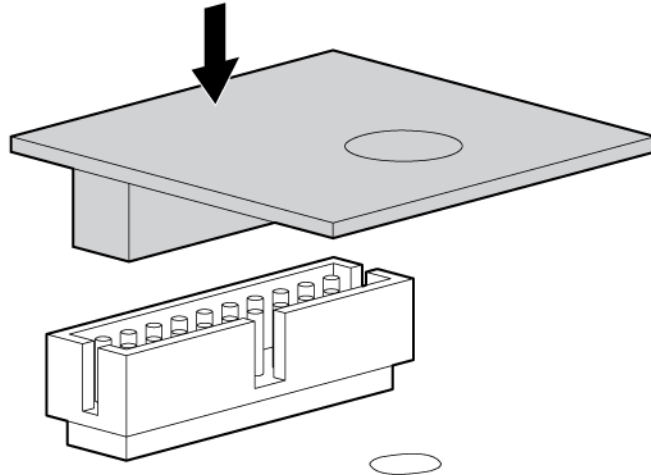
Installing the Trusted Platform Module board

 **WARNING:** To reduce the risk of personal injury from hot surfaces, allow the drives and the internal system components to cool before touching them.

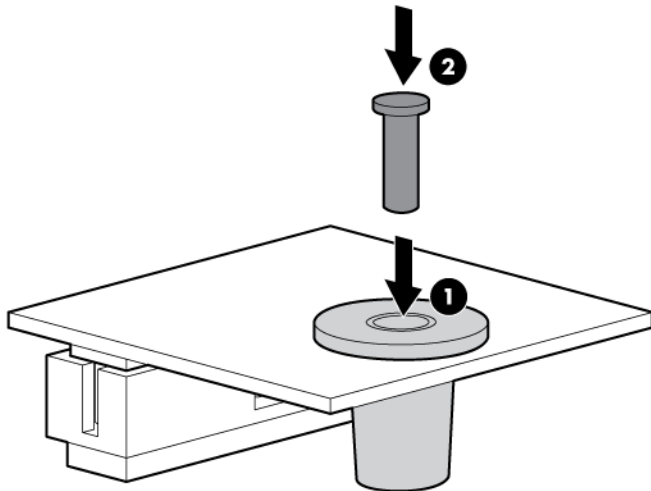
1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Place the server blade on a flat, level work surface.
4. Remove the access panel (on page 14).

 **CAUTION:** Any attempt to remove an installed TPM from the system board breaks or disfigures the TPM security rivet. Upon locating a broken or disfigured rivet on an installed TPM, administrators should consider the system compromised and take appropriate measures to ensure the integrity of the system data.

5. Install the TPM board. Press down on the connector to seat the board ("[System board components](#)" on page 8).



6. Install the TPM security rivet by pressing the rivet firmly into the system board.



7. Install the access panel.
8. Install the server blade ("[Installing a server blade](#)" on page 24).
9. Power up the server blade (on page 12).

Retaining the recovery key/password

The recovery key/password is generated during BitLocker™ setup, and can be saved and printed after BitLocker™ is enabled. When using BitLocker™, always retain the recovery key/password. The recovery key/password is required to enter Recovery Mode after BitLocker™ detects a possible compromise of system integrity.


To help ensure maximum security, observe the following guidelines when retaining the recovery key/password:

- Always store the recovery key/password in multiple locations.

- Always store copies of the recovery key/password away from the server blade.
- Do not save the recovery key/password on the encrypted hard drive.

Enabling the Trusted Platform Module

1. When prompted during the start-up sequence, access RBSU by pressing the **F9** key.
2. From the Main Menu, select **Server Security**.
3. From the Server Security Menu, select **Trusted Platform Module**.
4. From the Trusted Platform Module Menu, select **TPM Functionality**.
5. Select **Enable**, and then press the **Enter** key to modify the TPM Functionality setting.
6. Press the **Esc** key to exit the current menu, or press the **F10** key to exit RBSU.
7. Reboot the server blade.
8. Enable the TPM in the OS. For OS-specific instructions, see the OS documentation.

 **CAUTION:** When a TPM is installed and enabled on the server blade, data access is locked if you fail to follow the proper procedures for updating the system or option firmware, replacing the system board, replacing a hard drive, or modifying OS application TPM settings.

For more information on firmware updates and hardware procedures, see the *HP Trusted Platform Module Best Practices White Paper* on the HP website (<http://www.hp.com/support>).

For more information on adjusting TPM usage in BitLocker™, see the Microsoft website (<http://technet.microsoft.com/en-us/library/cc732774.aspx>).

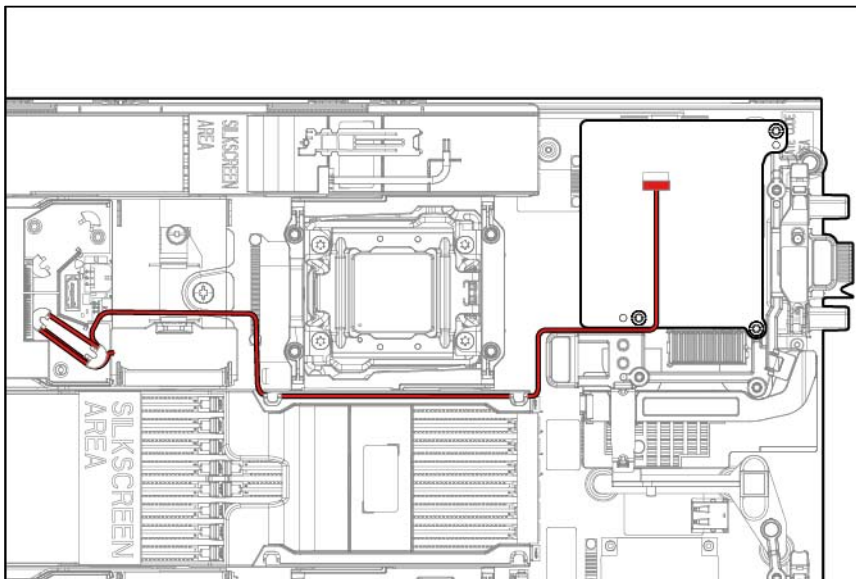
Cabling

Cabling resources

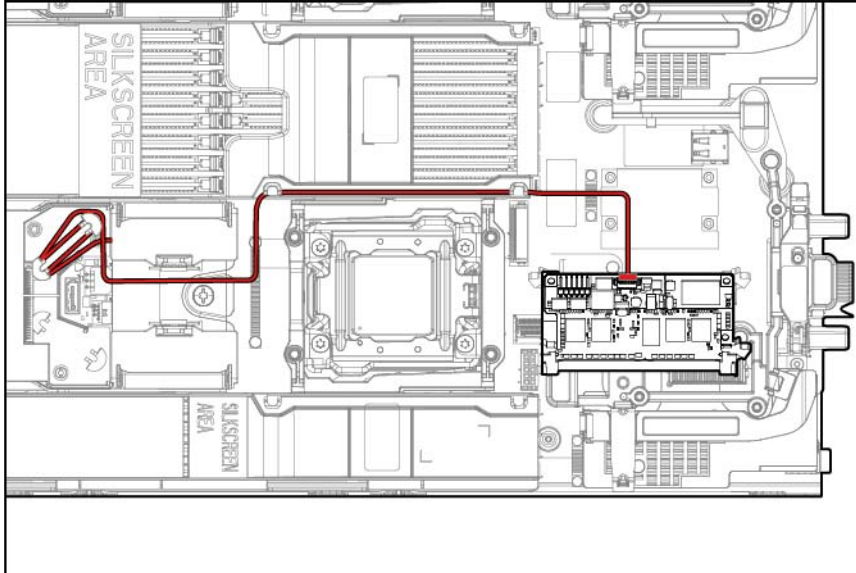
Cabling configurations and requirements vary depending on the product and installed options. For more information about product features, specifications, options, configurations, and compatibility, see the QuickSpecs on the HP website (<http://www.hp.com/go/productbulletin>). At the website, choose the geographic region, and then locate the product by name or product category.

FBWC capacitor pack cabling

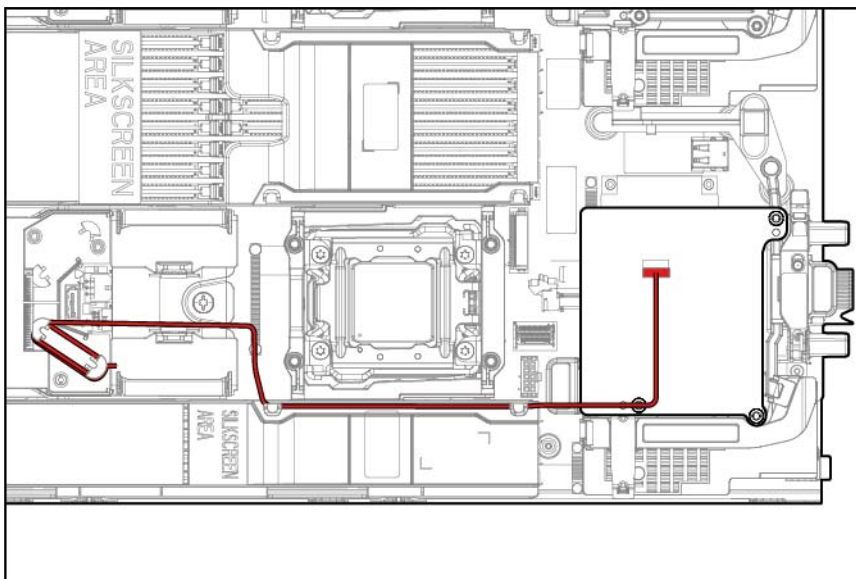
- FBWC capacitor pack cabling to the mezzanine 2 connector option



- FBWC capacitor pack cable to the cache module option



- FBWC capacitor pack cabling to the mezzanine 3 connector option



For capacitor pack and cabling instructions, see "FBWC capacitor pack options (on page 39)."

Using the HP c-Class Blade SUV Cable

The HP c-Class Blade SUV Cable enables the user to perform server blade administration, configuration, and diagnostic procedures by connecting video and USB devices directly to the server blade. For SUV cable connectors, see "HP c-Class Blade SUV Cable (on page 10)."

Connecting locally to a server blade with video and USB devices

Use the SUV cable to connect a monitor and any of the following USB devices:

- USB hub
- USB keyboard
- USB mouse
- USB CD/DVD-ROM drive

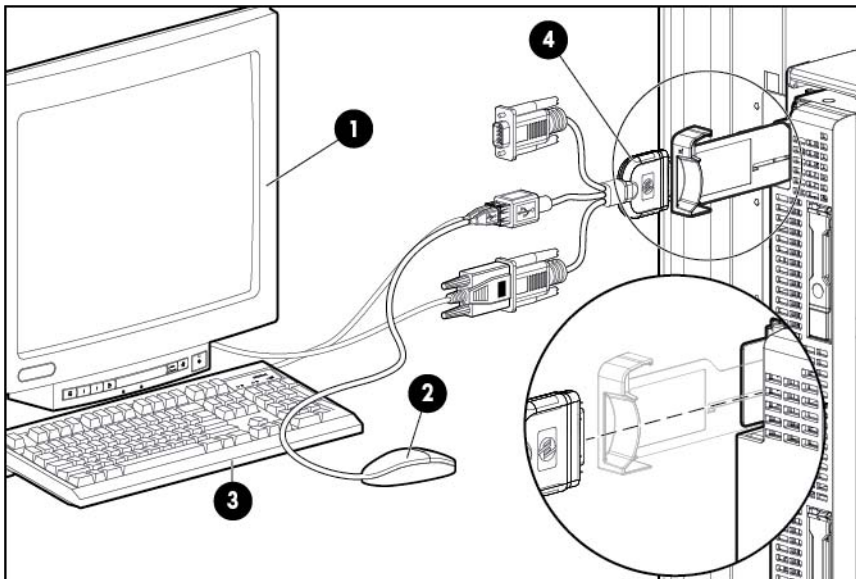
Numerous configurations are possible. This section offers two possible configurations. For more information, see "USB support (on page 59)."

Accessing a server blade with local KVM

For this configuration, a USB hub is not necessary. To connect additional devices, use a USB hub.

CAUTION: Before disconnecting the SUV cable from the connector, always squeeze the release buttons on the sides of the connector. Failure to do so can result in damage to the equipment.

1. Open the serial label pull tab and connect the HP c-Class Blade SUV Cable to the server blade.
2. Connect the video connector to a monitor.
3. Connect a USB mouse to one USB connector.
4. Connect a USB keyboard to the second USB connector.



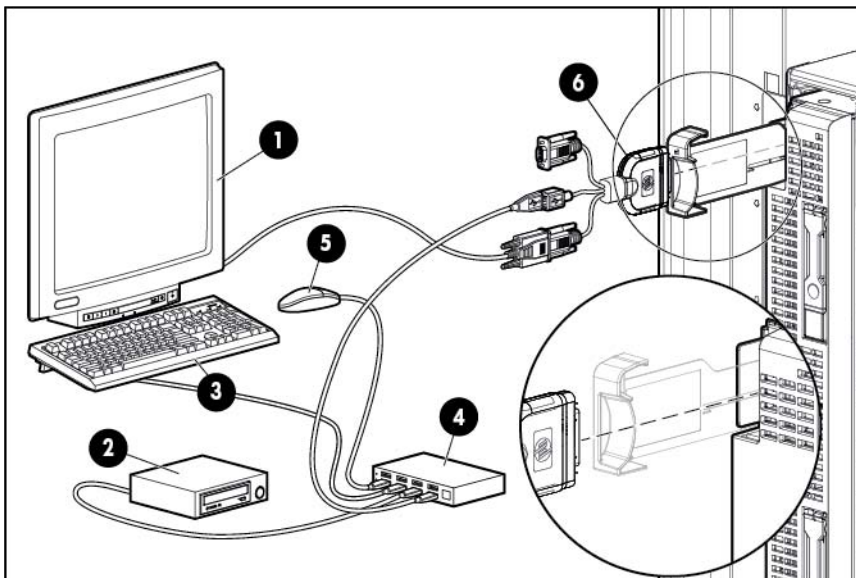
Item	Description
1	Monitor
2	USB mouse
3	USB keyboard
4	HP c-Class Blade SUV Cable

Accessing local media devices

Use the following configuration when configuring a server blade or loading software updates and patches from a USB CD/DVD-ROM.

Use a USB hub when connecting a USB CD-ROM drive to the server blade. The USB hub provides additional connections.

1. Open the serial label pull tab and connect the HP c-Class Blade SUV cable to the server blade.
2. Connect the video connector to a monitor.
3. Connect a USB keyboard to one USB connector.
4. Connect the following to the USB hub:
 - o USB CD/DVD-ROM drive
 - o USB keyboard
 - o USB mouse



Item	Description
1	Monitor
2	USB CD/DVD-ROM drive
3	USB keyboard
4	USB hub
5	USB mouse
6	HP c-Class Blade SUV Cable

Software and configuration utilities

Server mode

The software and configuration utilities presented in this section operate in online mode, offline mode, or in both modes.

Software or configuration utility	Server mode
HP iLO (on page 50)	Online and Offline
Active Health System (on page 51)	Online and Offline
Integrated Management Log (on page 52)	Online and Offline
Intelligent Provisioning (on page 52)	Offline
HP Insight Diagnostics (on page 53)	Online and Offline
HP Insight Remote Support software (on page 54)	Online
Erase Utility (on page 53)	Offline
Scripting Toolkit (on page 54)	Online
HP Service Pack for ProLiant (on page 55)	Online and Offline
HP Smart Update Manager (on page 55)	Online and Offline
HP ROM-Based Setup Utility (on page 55)	Offline
Array Configuration Utility (on page 58)	Online and Offline
Option ROM Configuration for Arrays (on page 59)	Offline
ROMPaq utility (on page 59)	Offline

Server QuickSpecs

For more information about product features, specifications, options, configurations, and compatibility, see the QuickSpecs on the HP website (<http://www.hp.com/go/productbulletin>). At the website, choose the geographic region, and then locate the product by name or product category.

HP iLO Management Engine

The HP iLO Management Engine is a set of embedded management features supporting the complete lifecycle of the server blade, from initial deployment through ongoing management.

HP iLO

The iLO subsystem is a standard component of selected HP ProLiant servers that simplifies initial server blade setup, server health monitoring, power and thermal optimization, and remote server administration. The iLO subsystem includes an intelligent microprocessor, secure memory, and a dedicated network interface. This design makes iLO independent of the host server and its operating system.

iLO enables and manages the Active Health System (on page 51) and also features Agentless Management. All key internal subsystems are monitored by iLO. SNMP alerts are sent directly by iLO regardless of the host operating system or even if no host operating system is installed.

HP Insight Remote Support software (on page 54) is also available in HP iLO with no operating system software, drivers, or agents.

Using iLO, you can do the following:

- Access a high-performance and secure Remote Console to the server from anywhere in the world.
- Use the shared iLO Remote Console to collaborate with up to six server administrators.
- Remotely mount high-performance Virtual Media devices to the server blade.
- Securely and remotely control the power state of the managed server blade.
- Have true Agentless Management with SNMP alerts from iLO regardless of the state of the host server blade.
- Access Active Health System troubleshooting features through the iLO interface.
- Subscribe to HP Insight Remote Support software without installing any drivers or agents.

For more information about iLO features (which may require an iLO Advanced Pack or iLO Advanced for BladeSystem license), see the iLO documentation on the Documentation CD or on the HP website (<http://www.hp.com/go/ilo/docs>).

Active Health System

HP Active Health System provides the following features:

- Combined diagnostics tools/scanners
- Always on, continuous monitoring for increased stability and shorter downtimes
- Rich configuration history
- Health and service alerts
- Easy export and upload to Service and Support

The HP Active Health System monitors and records changes in the server hardware and system configuration. The Active Health System assists in diagnosing problems and delivering rapid resolution when server failures occur.

The Active Health System collects the following types of data:

- Server model
- Serial number
- Processor model and speed
- Storage capacity and speed
- Memory capacity and speed
- Firmware/BIOS

HP Active Health System does not collect information about Active Health System users' operations, finances, customers, employees, partners, or data center, such as IP addresses, host names, user names, and passwords. HP Active Health System does not parse or change operating system data from third-party error event log activities, such as content created or passed through by the operating system.

The data that is collected is managed according to the HP Data Privacy policy. For more information see the HP website (<http://www.hp.com/go/privacy>).

The Active Health System log, in conjunction with the system monitoring provided by Agentless Management or SNMP Pass-thru, provides continuous monitoring of hardware and configuration changes, system status, and service alerts for various server components.

The Agentless Management Service is available in the SPP, which is a disk image (.iso) that you can download from the HP website (<http://www.hp.com/go/spp/download>). The Active Health System log can be downloaded manually from iLO or HP Intelligent Provisioning and sent to HP. For more information, see the *HP iLO User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).

Integrated Management Log

The IML records hundreds of events and stores them in an easy-to-view form. The IML timestamps each event with 1-minute granularity.

You can view recorded events in the IML in several ways, including the following:

- From within HP SIM
- From within operating system-specific IML viewers
 - For Windows: IML Viewer
 - For Linux: IML Viewer Application
- From within the iLO user interface
- From within HP Insight Diagnostics (on page 53)

Intelligent Provisioning

Several packaging changes have taken place with HP ProLiant Gen8 servers: SmartStart CDs and the Smart Update Firmware DVD will no longer ship with these new server blades. Instead, the deployment capability is embedded in the server blade as part of HP iLO Management Engine's Intelligent Provisioning.

Intelligent Provisioning is an essential single-server deployment tool embedded in HP ProLiant Gen8 servers that simplifies HP ProLiant server setup, providing a reliable and consistent way to deploy HP ProLiant server configurations.

- Intelligent Provisioning assists with the OS installation process by preparing the system for installing "off-the-shelf" versions of leading operating system software and automatically integrating optimized HP ProLiant server support software from SPP. SPP is the installation package for operating system-specific bundles of HP ProLiant optimized drivers, utilities, management agents, and system firmware.
- Intelligent Provisioning provides maintenance-related tasks through Perform Maintenance features.
- Intelligent Provisioning provides installation help for Microsoft Windows, Red Hat and SUSE Linux, and VMware. For specific OS support, see the *HP Intelligent Provisioning Release Notes*.

For more information on Intelligent Provisioning software, see the HP website (<http://www.hp.com/go/ilo>). For more information about Intelligent Provisioning drivers, firmware, and SPP, see the HP website (<http://www.hp.com/go/spp/download>).

HP Insight Diagnostics

HP Insight Diagnostics is a proactive server blade management tool, available in both offline and online versions, that provides diagnostics and troubleshooting capabilities to assist IT administrators who verify server blade installations, troubleshoot problems, and perform repair validation.

HP Insight Diagnostics Offline Edition performs various in-depth system and component testing while the OS is not running. To run this utility, boot the server blade using Intelligent Provisioning (on page 52).

HP Insight Diagnostics Online Edition is a web-based application that captures system configuration and other related data needed for effective server blade management. Available in Microsoft Windows and Linux versions, the utility helps to ensure proper system operation.

For more information or to download the utility, see the HP website (<http://www.hp.com/servers/diags>). HP Insight Diagnostics Online Edition is also available in the SPP. For more information, see the HP website (<http://www.hp.com/go/spp/download>).

HP Insight Diagnostics survey functionality

HP Insight Diagnostics (on page 53) provides survey functionality that gathers critical hardware and software information on ProLiant server blades.

This functionality supports operating systems that are supported by the server blade. For operating systems supported by the server blade, see the HP website (<http://www.hp.com/go/supportos>).

If a significant change occurs between data-gathering intervals, the survey function marks the previous information and overwrites the survey data files to reflect the latest changes in the configuration.

Survey functionality is installed with every Intelligent Provisioning-assisted HP Insight Diagnostics installation, or it can be installed through the SPP ("HP Service Pack for ProLiant" on page 55).

Erase Utility



CAUTION: Perform a backup before running the System Erase Utility. The utility sets the system to its original factory state, deletes the current hardware configuration information, including array setup and disk partitioning, and erases all connected hard drives completely. Refer to the instructions for using this utility.

The Erase utility enables you to erase system CMOS, NVRAM, and hard drives. Run the Erase Utility if you must erase the system for the following reasons:

- You want to install a new operating system on a server blade with an existing operating system.
- You encounter an error when completing the steps of a factory-installed operating system installation.

To access the Erase Utility, click the Perform Maintenance icon from the Intelligent Provisioning home screen and then select **Erase**.

Run the Erase utility to:

- **Reset all settings** — erases all drives, NVRAM, and RBSU
- **Reset all disks** — erases all drives
- **Reset RBSU** — erases current RBSU settings

After selecting the appropriate option, click **Erase System**. Click **Exit** to reboot the server after the erase task is completed. Click **Cancel Erase** to exit the utility without erasing.

HP Insight Remote Support software

HP strongly recommends that you install HP Insight Remote Support software to complete the installation or upgrade of your product and to enable enhanced delivery of your HP Warranty, HP Care Pack Service, or HP contractual support agreement. HP Insight Remote Support supplements your monitoring 24 x 7 to ensure maximum system availability by providing intelligent event diagnosis, and automatic, secure submission of hardware event notifications to HP, which will initiate a fast and accurate resolution, based on your product's service level. Notifications may be sent to your authorized HP Channel Partner for on-site service, if configured and available in your country. The software is available in two variants:

- **HP Insight Remote Support Standard:** This software supports server and storage devices and is optimized for environments with 1–50 servers. Ideal for customers who can benefit from proactive notification but do not need proactive service delivery and integration with a management platform.
- **HP Insight Remote Support Advanced:** For customers with mid-size to large environments with over 500 devices who require HP Proactive Services, or customers currently using HP Operations Manager or SAP Solution Manager to manage their environment, HP recommends installing the latest HP Insight Remote Support Advanced software. This software provides comprehensive remote monitoring and proactive service support for nearly all HP servers, storage, network, and SAN environments, plus selected non-HP servers that have a support obligation with HP. It is integrated with HP Systems Insight Manager. A dedicated server is recommended to host both HP Systems Insight Manager and HP Insight Remote Support Advanced.

Details for both versions are available on the HP website (<http://www.hp.com/go/insightremotesupport>).

To download the software, go to Software Depot (<http://www.software.hp.com>).

Select **Insight Remote Support** from the menu on the right.

The HP Insight Remote Support software release notes detail the specific prerequisites, supported hardware, and associated operating systems. For more information:

- See the HP Insight Remote Support Standard Release Notes on the HP website (<http://www.hp.com/go/insightremotestandard-docs>).
- See the HP Insight Remote Support Advanced Release Notes on the HP website (<http://www.hp.com/go/insightremoteadvanced-docs>).

Scripting Toolkit

The Scripting Toolkit is a server deployment product that enables you to build an unattended automated installation for high-volume server deployments. The Scripting Toolkit is designed to support ProLiant BL, ML, DL, and SL servers. The toolkit includes a modular set of utilities and important documentation that describes how to apply these tools to build an automated server deployment process.

The Scripting Toolkit provides a flexible way to create standard server configuration scripts. These scripts are used to automate many of the manual steps in the server configuration process. This automated server configuration process cuts time from each deployment, making it possible to scale rapid, high-volume server deployments.

For more information, and to download the Scripting Toolkit, see the HP website (<http://www.hp.com/go/ProLiantSTK>).

HP Service Pack for ProLiant

SPP is a release set that contains a comprehensive collection of firmware and system software components, all tested together as a single solution stack for HP ProLiant servers, their options, BladeSystem enclosures, and limited HP external storage.

SPP has several key features for updating HP ProLiant servers. Using HP SUM as the deployment tool, SPP can be used in an online mode on a Windows or Linux hosted operating system, or in an offline mode where the server is booted to the ISO so that the server can be updated automatically with no user interaction or updated in interactive mode.

For more information or to download SPP, see the HP website (<http://www.hp.com/go/spp>).

HP Smart Update Manager

The HP SUM provides intelligent and flexible firmware and software deployment. This technology assists in reducing the complexity of provisioning and updating HP ProLiant Servers, options, and Blades within the data center. HP SUM is used to deploy firmware and software in SPP.

HP SUM enables system administrators to upgrade ROM images efficiently across a wide range of server blades and options. This tool has the following features:

- Enables GUI and a command-line, scriptable interface
- Provides scriptable, command-line deployment
- Requires no agent for remote installations
- Enables dependency checking, which ensures appropriate install order and dependency checking between components
- Deploys software and firmware on Windows and Linux operating systems
- Performs local or remote (one-to-many) online deployment
- Deploys firmware and software together
- Supports offline and online deployment
- Deploys necessary component updates only
- Downloads the latest components from Web
- Enables direct update of BMC firmware (HP iLO)

For more information about HP SUM and to access the *HP Smart Update Manager User Guide*, see the HP website (<http://www.hp.com/go/hpsum/documentation>).

HP ROM-Based Setup Utility

RBSU is a configuration utility embedded in ProLiant servers that performs a wide range of configuration activities that can include the following:

- Configuring system devices and installed options
- Enabling and disabling system features
- Displaying system information
- Selecting the primary boot controller

- Configuring memory options
- Language selection

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

Using RBSU

To use RBSU, use the following keys:

- To access RBSU, press the **F9** key during power-up when prompted.
- To navigate the menu system, use the arrow keys.
- To make selections, press the **Enter** key.
- To access Help for a highlighted configuration option, press the **F1** key.



IMPORTANT: RBSU automatically saves settings when you press the **Enter** key. The utility does not prompt you for confirmation of settings before you exit the utility. To change a selected setting, you must select a different setting and press the **Enter** key.

Default configuration settings are applied to the server at one of the following times:

- Upon the first system power-up
- After defaults have been restored

Default configuration settings are sufficient for proper typical server operation, but configuration settings can be modified using RBSU. The system will prompt you for access to RBSU with each power-up.

Auto-configuration process

The auto-configuration process automatically runs when you boot the server for the first time. During the power-up sequence, the system ROM automatically configures the entire system without needing any intervention. During this process, the ORCA utility, in most cases, automatically configures the array to a default setting based on the number of drives connected to the server.

NOTE: If the boot drive is not empty or has been written to in the past, ORCA does not automatically configure the array. You must run ORCA to configure the array settings.

NOTE: The server may not support all the following examples.

Drives installed	Drives used	RAID level
1	1	RAID 0
2	2	RAID 1
3, 4, 5, or 6	3, 4, 5, or 6	RAID 5
More than 6	0	None

To change any ORCA default settings and override the auto-configuration process, press the **F8** key when prompted.

For more information on RBSU, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

Boot options

Near the end of the boot process, the boot options screen is displayed. This screen is visible for several seconds before the system attempts to boot from a supported boot device. During this time, you can do the following:

- Access RBSU by pressing the **F9** key.
- Access Intelligent Provisioning Maintenance Menu by pressing the **F10** key.
- Access the boot menu by pressing the **F11** key.
- Force a PXE Network boot by pressing the **F12** key.

Configuring AMP modes

Not all ProLiant servers support all AMP modes. RBSU provides menu options only for the modes supported by the server. Advanced memory protection within RBSU enables the following advanced memory modes:

- **Advanced ECC Mode**—Provides memory protection beyond Standard ECC. All single-bit failures and some multi-bit failures can be corrected without resulting in system downtime.
- **Online Spare Mode**—Provides protection against failing or degraded DIMMs. Certain memory is set aside as spare, and automatic failover to spare memory occurs when the system detects a degraded DIMM. DIMMs that are likely to receive a fatal or uncorrectable memory error are removed from operation automatically, resulting in less system downtime.

For DIMM population requirements, see the server-specific user guide.

Re-entering the server serial number and product ID

After you replace the system board, you must re-enter the server blade serial number and the product ID.

1. During the server blade startup sequence, press the **F9** key to access RBSU.
2. Select the **Advanced Options** menu.
3. Select **Service Options**.
4. Select **Serial Number**. The following warning appears:
`Warning: The serial number should ONLY be modified by qualified service personnel. This value should always match the serial number located on the chassis.`
5. Press the **Enter** key to clear the warning.
6. Enter the serial number and press the **Enter** key.
7. Select **Product ID**. The following warning appears:
`Warning: The Product ID should ONLY be modified by qualified service personnel. This value should always match the Product ID located on the chassis.`
8. Enter the product ID and press the **Enter** key.
9. Press the **Esc** key to close the menu.
10. Press the **Esc** key to exit RBSU.
11. Press the **F10** key to confirm exiting RBSU. The server blade automatically reboots.

Utilities and features

Array Configuration Utility

ACU is a utility with the following features:

- Runs as a local application or remote service accessed through the HP System Management Homepage
- Supports online array capacity expansion, logical drive extension, assignment of online spares, and RAID or stripe size migration
- Suggests the optimum configuration for an unconfigured system
- For supported controllers, provides access to licensed features, including:
 - Moving and deleting individual logical volumes
 - Advanced Capacity Expansion (SATA to SAS and SAS to SATA)
 - Offline Split Mirror
 - RAID 6 and RAID 60
 - RAID 1 (ADM) and RAID 10 (ADM)
 - HP Drive Erase
 - Video-On-Demand Advanced Controller Settings
- Provides different operating modes, enabling faster configuration or greater control over the configuration options
- Remains available any time that the server is on
- Displays on-screen tips for individual steps of a configuration procedure
- Provides context-sensitive searchable help content
- Provides diagnostic and SmartSSD Wear Gauge functionality on the Diagnostics tab

ACU is now available as an embedded utility, starting with HP ProLiant Gen8 servers. To access ACU, use one of the following methods:

- If an optional controller is not installed, press **F10** during boot.
- If an optional controller is installed, when the system recognizes the controller during POST, press **F5**.

For optimum performance, the minimum display settings are 1024 × 768 resolution and 16-bit color. Servers running Microsoft® operating systems require one of the following supported browsers:

- Internet Explorer 6.0 or later
- Mozilla Firefox 2.0 or later

For Linux servers, see the README.TXT file for additional browser and support information.

For more information about the controller and its features, see the *HP Smart Array Controllers for HP ProLiant Servers User Guide* on the HP website (http://www.hp.com/support/SAC_UG_ProLiantServers_en). To configure arrays, see the *Configuring Arrays on HP Smart Array Controllers Reference Guide* on the HP website (http://www.hp.com/support/CASAC_RG_en).

Option ROM Configuration for Arrays

Before installing an operating system, you can use the ORCA utility to create the first logical drive, assign RAID levels, and establish online spare configurations.

The utility also provides support for the following functions:

- Reconfiguring one or more logical drives
- Viewing the current logical drive configuration
- Deleting a logical drive configuration
- Setting the controller to be the boot controller
- Selecting the boot volume

If you do not use the utility, ORCA will default to the standard configuration.

For more information regarding the default configurations that ORCA uses, see the *HP ROM-Based Setup Utility User Guide* on the Documentation CD or the HP website (<http://www.hp.com/support/rbsu>).

For more information about the controller and its features, see the *HP Smart Array Controllers for HP ProLiant Servers User Guide* on the HP website (http://www.hp.com/support/SAC_UG_ProLiantServers_en). To configure arrays, see the *Configuring Arrays on HP Smart Array Controllers Reference Guide* on the HP website (http://www.hp.com/support/CASAC_RG_en).

ROMPaq utility

The ROMPaq utility enables you to upgrade the system firmware (BIOS). To upgrade the firmware, insert a ROMPaq USB Key into an available USB port and boot the system. In addition to ROMPaq, Online Flash Components for Windows and Linux operating systems are available for updating the system firmware.

The ROMPaq utility checks the system and provides a choice (if more than one exists) of available firmware revisions.

For more information, go to the HP website (<http://www.hp.com/go/hpsc>) and click on **Drivers, Software & Firmware**. Then, enter your product name in the **Find an HP product** field and click **Go**.

Automatic Server Recovery

ASR is a feature that causes the system to restart when a catastrophic operating system error occurs, such as a blue screen, ABEND (does not apply to HP ProLiant DL980 Servers), or panic. A system fail-safe timer, the ASR timer, starts when the System Management driver, also known as the Health Driver, is loaded. When the operating system is functioning properly, the system periodically resets the timer. However, when the operating system fails, the timer expires and restarts the server.

ASR increases server availability by restarting the server within a specified time after a system hang. At the same time, the HP SIM console notifies you by sending a message to a designated pager number that ASR has restarted the system. You can disable ASR from the System Management Homepage or through RBSU.

USB support

HP provides both standard USB 2.0 support and legacy USB 2.0 support. Standard support is provided by the OS through the appropriate USB device drivers. Before the OS loads, HP provides support for USB devices through legacy USB support, which is enabled by default in the system ROM.

Legacy USB support provides USB functionality in environments where USB support is not available normally. Specifically, HP provides legacy USB functionality for the following:

- POST
- RBSU
- Diagnostics
- DOS
- Operating environments which do not provide native USB support

Redundant ROM support

The server blade enables you to upgrade or configure the ROM safely with redundant ROM support. The server blade has a single ROM that acts as two separate ROM images. In the standard implementation, one side of the ROM contains the current ROM program version, while the other side of the ROM contains a backup version.

NOTE: The server ships with the same version programmed on each side of the ROM.

Safety and security benefits

When you flash the system ROM, ROMPaq writes over the backup ROM and saves the current ROM as a backup, enabling you to switch easily to the alternate ROM version if the new ROM becomes corrupted for any reason. This feature protects the existing ROM version, even if you experience a power failure while flashing the ROM.

Keeping the system current

Drivers



IMPORTANT: Always perform a backup before installing or updating device drivers.

The server blade includes new hardware that may not have driver support on all OS installation media.

If you are installing an Intelligent Provisioning-supported OS, use Intelligent Provisioning (on page 52) and its Configure and Install feature to install the OS and latest supported drivers.

If you do not use Intelligent Provisioning to install an OS, drivers for some of the new hardware are required. These drivers, as well as other option drivers, ROM images, and value-add software can be downloaded as part of an SPP.

If you are installing drivers from SPP, be sure that you are using the latest SPP version that your server blade supports. To verify that your server blade is using the latest supported version and for more information about SPP, see the HP website (<http://www.hp.com/go/spp/download>).

To locate the drivers for a particular server, go to the HP website (<http://www.hp.com/go/hpsc>) and click on **Drivers, Software & Firmware**. Then, enter your product name in the **Find an HP product** field and click **Go**.

Software and firmware

Software and firmware should be updated before using the server for the first time, unless any installed software or components require an older version. For system software and firmware updates, download the SPP ("HP Service Pack for ProLiant" on page 55) from the HP website (<http://www.hp.com/go/spp>).

Version control

The VCRM and VCA are web-enabled Insight Management Agents tools that HP SIM uses to schedule software update tasks to the entire enterprise.

- VCRM manages the repository for SPP. Administrators can view the SPP contents or configure VCRM to automatically update the repository with internet downloads of the latest software and firmware from HP.
- VCA compares installed software versions on the node with updates available in the VCRM managed repository. Administrators configure VCA to point to a repository managed by VCRM.

For more information about version control tools, see the *HP Systems Insight Manager User Guide*, the *HP Version Control Agent User Guide*, and the *HP Version Control Repository User Guide* on the HP website (<http://www.hp.com/go/hpsim>).

HP Operating Systems and Virtualization Software Support for ProLiant Servers

For information about specific versions of a supported operating system, see the HP website (<http://www.hp.com/go/ossupport>).

Change control and proactive notification

HP offers Change Control and Proactive Notification to notify customers 30 to 60 days in advance of upcoming hardware and software changes on HP commercial products.

For more information, refer to the HP website (<http://www.hp.com/go/pcn>).

Troubleshooting

Troubleshooting resources

The *HP ProLiant Gen8 Troubleshooting Guide, Volume I: Troubleshooting* provides procedures for resolving common problems and comprehensive courses of action for fault isolation and identification, issue resolution, and software maintenance on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_TSG_v1_en)
- French (http://www.hp.com/support/ProLiant_TSG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_TSG_v1_sp)
- German (http://www.hp.com/support/ProLiant_TSG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_TSG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_TSG_v1_sc)

The *HP ProLiant Gen8 Troubleshooting Guide, Volume II: Error Messages* provides a list of error messages and information to assist with interpreting and resolving error messages on ProLiant servers and server blades. To view the guide, select a language:

- English (http://www.hp.com/support/ProLiant_EMG_v1_en)
- French (http://www.hp.com/support/ProLiant_EMG_v1_fr)
- Spanish (http://www.hp.com/support/ProLiant_EMG_v1_sp)
- German (http://www.hp.com/support/ProLiant_EMG_v1_gr)
- Japanese (http://www.hp.com/support/ProLiant_EMG_v1_jp)
- Simplified Chinese (http://www.hp.com/support/ProLiant_EMG_v1_sc)

Battery replacement

If the server blade no longer automatically displays the correct date and time, you might have to replace the battery that provides power to the real-time clock. Under normal use, battery life is 5 to 10 years.

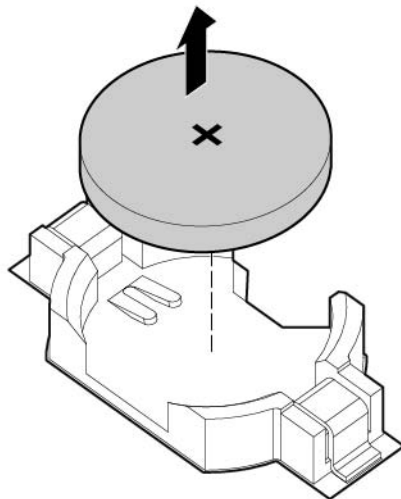


WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
 - Do not expose the battery to temperatures higher than 60°C (140°F).
 - Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.
 - Replace only with the spare designated for this product.
-

To remove the component:

1. Power down the server blade (on page 12).
2. Remove the server blade (on page 13).
3. Access the internal server components.
4. Identify the battery location ("[System board components](#)" on page 8).
5. Remove the system battery.



IMPORTANT: Replacing the system board battery resets the system ROM to its default configuration. After replacing the battery, reconfigure the system through RBSU.

To replace the component, reverse the removal procedure.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Regulatory compliance notices

Regulatory compliance identification numbers

For the purpose of regulatory compliance certifications and identification, this product has been assigned a unique regulatory model number. The regulatory model number can be found on the product nameplate label, along with all required approval markings and information. When requesting compliance information for this product, always refer to this regulatory model number. The regulatory model number is not the marketing name or model number of the product.

Federal Communications Commission notice

Part 15 of the Federal Communications Commission (FCC) Rules and Regulations has established Radio Frequency (RF) emission limits to provide an interference-free radio frequency spectrum. Many electronic devices, including computers, generate RF energy incidental to their intended function and are, therefore, covered by these rules. These rules place computers and related peripheral devices into two classes, A and B, depending upon their intended installation. Class A devices are those that may reasonably be expected to be installed in a business or commercial environment. Class B devices are those that may reasonably be expected to be installed in a residential environment (for example, personal computers). The FCC requires devices in both classes to bear a label indicating the interference potential of the device as well as additional operating instructions for the user.

FCC rating label

The FCC rating label on the device shows the classification (A or B) of the equipment. Class B devices have an FCC logo or ID on the label. Class A devices do not have an FCC logo or ID on the label. After you determine the class of the device, refer to the corresponding statement.

FCC Notice, Class A Equipment

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference, in which case the user will be required to correct the interference at personal expense.

FCC Notice, Class B Equipment

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to

radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit that is different from that to which the receiver is connected.
- Consult the dealer or an experienced radio or television technician for help.

Declaration of conformity for products marked with the FCC logo, United States only

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

For questions regarding this product, contact us by mail or telephone:

- Hewlett-Packard Company
P. O. Box 692000, Mail Stop 530113
Houston, Texas 77269-2000
- 1-800-HP-INVENT (1-800-474-6836). (For continuous quality improvement, calls may be recorded or monitored.)

For questions regarding this FCC declaration, contact us by mail or telephone:

- Hewlett-Packard Company
P. O. Box 692000, Mail Stop 510101
Houston, Texas 77269-2000
- 1-281-514-3333

To identify this product, refer to the part, series, or model number found on the product.

Modifications

The FCC requires the user to be notified that any changes or modifications made to this device that are not expressly approved by Hewlett-Packard Company may void the user's authority to operate the equipment.

Cables

Connections to this device must be made with shielded cables with metallic RFI/EMI connector hoods in order to maintain compliance with FCC Rules and Regulations.

Canadian notice (Avis Canadien)

Class A equipment

This Class A digital apparatus meets all requirements of the Canadian Interference-Causing Equipment Regulations.

Cet appareil numérique de la classe A respecte toutes les exigences du Règlement sur le matériel brouilleur du Canada.

Class B equipment

This Class B digital apparatus meets all requirements of the Canadian Interference-Causing Equipment Regulations.

Cet appareil numérique de la classe B respecte toutes les exigences du Règlement sur le matériel brouilleur du Canada.

European Union regulatory notice

Products bearing the CE marking comply with the following EU Directives:

- Low Voltage Directive 2006/95/EC
- EMC Directive 2004/108/EC
- Ecodesign Directive 2009/125/EC, where applicable

CE compliance of this product is valid if powered with the correct CE-marked AC adapter provided by HP.

Compliance with these directives implies conformity to applicable harmonized European standards (European Norms) that are listed in the EU Declaration of Conformity issued by HP for this product or product family and available (in English only) either within the product documentation or at the following HP website (<http://www.hp.eu/certificates>) (type the product number in the search field).

The compliance is indicated by one of the following conformity markings placed on the product:

For non-telecommunications products and for EU harmonized telecommunications products, such as Bluetooth® within power class below 10mW.



For EU non-harmonized telecommunications products (If applicable, a 4-digit notified body number is inserted between CE and !).



Please refer to the regulatory label provided on the product.

The point of contact for regulatory matters is Hewlett-Packard GmbH, Dept./MS: HQ-TRE, Herrenberger Strasse 140, 71034 Boeblingen, GERMANY.

Disposal of waste equipment by users in private households in the European Union



This symbol on the product or on its packaging indicates that this product must not be disposed of with your other household waste. Instead, it is your responsibility to dispose of your waste equipment by handing it over to a designated collection point for the recycling of waste electrical and electronic equipment. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment for recycling, please contact your local city office, your household waste disposal service or the shop where you purchased the product.

Japanese notice

ご使用になっている装置に VCCI マークが付いていましたら、次の説明文をお読み下さい。

この装置は、クラス B 情報技術装置です。この装置は、家庭環境で使用することを目的としていますが、この装置がラジオやテレビジョン受信機に近接して使用されると、受信障害を引き起こすことがあります。取扱説明書に従って正しい取り扱いをして下さい。

VCCI-B

VCCI マークが付いていない場合には、次の点にご注意下さい。

この装置は、クラス A 情報技術装置です。この装置を家庭環境で使用すると電波妨害を引き起こすことがあります。この場合には使用者は適切な対策を講ずるよう要求されることがあります。

VCCI-A

BSMI notice

警告使用者:

這是甲類的資訊產品，在居住的環境中使用時，可能會造成射頻干擾，在這種情況下，使用者會被要求採取某些適當的對策。

Korean notice

Class A equipment

A급 기기 (업무용 방송통신기기)	이 기기는 업무용(A급)으로 전자파적합등록을 한 기기이오니 판매자 또는 사용자는 이 점을 주의하시기 바라며, 가정 외의 지역에서 사용하는 것을 목적으로 합니다.
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Class B equipment

B급 기기 (가정용 방송통신기기)	이 기기는 가정용(B급)으로 전자파적합등록을 한 기기로서 주로 가정에서 사용하는 것을 목적으로 하며, 모든 지역에서 사용할 수 있습니다.
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Chinese notice

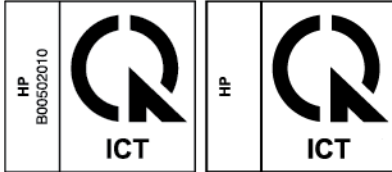
Class A equipment

声明

此为 A 级产品，在生活环境中，该产品可能会造成无线电干扰。在这种情况下，可能需要用户对其干扰采取可行的措施。

Vietnam compliance marking notice

This marking is for applicable products only.



Ukraine notice

Україна

Додаток до документації користувача

Обладнання відповідає вимогам Технічного регламенту щодо обмеження використання деяких небезпечних речовин в електричному та електронному обладнанні, затвердженого постановою Кабінету Міністрів України від 3 грудня 2008 № 1057

Збережіть цей документ разом із документацією користувача для цього виробу

Laser compliance

This product may be provided with an optical storage device (that is, CD or DVD drive) and/or fiber optic transceiver. Each of these devices contains a laser that is classified as a Class 1 Laser Product in accordance with US FDA regulations and the IEC 60825-1. The product does not emit hazardous laser radiation.

Each laser product complies with 21 CFR 1040.10 and 1040.11 except for deviations pursuant to Laser Notice No. 50, dated June 24, 2007; and with IEC 60825-1:2007.



WARNING: Use of controls or adjustments or performance of procedures other than those specified herein or in the laser product's installation guide may result in hazardous radiation exposure. To reduce the risk of exposure to hazardous radiation:

- Do not try to open the module enclosure. There are no user-serviceable components inside.
- Do not operate controls, make adjustments, or perform procedures to the laser device other than those specified herein.
- Allow only HP Authorized Service technicians to repair the unit.

The Center for Devices and Radiological Health (CDRH) of the U.S. Food and Drug Administration implemented regulations for laser products on August 2, 1976. These regulations apply to laser products manufactured from August 1, 1976. Compliance is mandatory for products marketed in the United States.

Battery replacement notice



WARNING: The computer contains an internal lithium manganese dioxide, a vanadium pentoxide, or an alkaline battery pack. A risk of fire and burns exists if the battery pack is not properly handled. To reduce the risk of personal injury:

- Do not attempt to recharge the battery.
- Do not expose the battery to temperatures higher than 60°C (140°F).
- Do not disassemble, crush, puncture, short external contacts, or dispose of in fire or water.

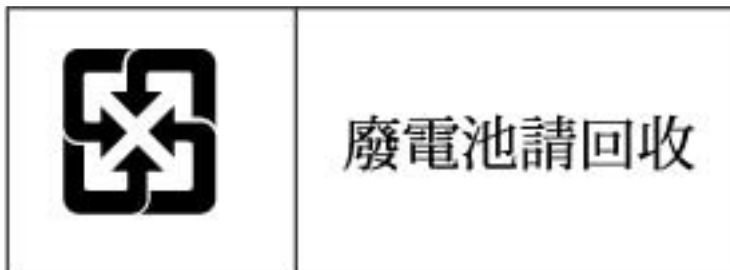


Batteries, battery packs, and accumulators should not be disposed of together with the general household waste. To forward them to recycling or proper disposal, use the public collection system or return them to HP, an authorized HP Partner, or their agents.

For more information about battery replacement or proper disposal, contact an authorized reseller or an authorized service provider.

Taiwan battery recycling notice

The Taiwan EPA requires dry battery manufacturing or importing firms in accordance with Article 15 of the Waste Disposal Act to indicate the recovery marks on the batteries used in sales, giveaway or promotion. Contact a qualified Taiwanese recycler for proper battery disposal.



Acoustics statement for Germany (Geräuschemission)

Schalldruckpegel $L_{pA} < 70$ dB(A)

Zuschauerpositionen (bystander positions), Normaler Betrieb (normal operation)

Nach ISO 7779:1999 (Typprüfung)

Electrostatic discharge

Preventing electrostatic discharge

To prevent damaging the system, be aware of the precautions you need to follow when setting up the system or handling parts. A discharge of static electricity from a finger or other conductor may damage system boards or other static-sensitive devices. This type of damage may reduce the life expectancy of the device.

To prevent electrostatic damage:

- Avoid hand contact by transporting and storing products in static-safe containers.
- Keep electrostatic-sensitive parts in their containers until they arrive at static-free workstations.
- Place parts on a grounded surface before removing them from their containers.
- Avoid touching pins, leads, or circuitry.
- Always be properly grounded when touching a static-sensitive component or assembly.

Grounding methods to prevent electrostatic discharge

Several methods are used for grounding. Use one or more of the following methods when handling or installing electrostatic-sensitive parts:

- Use a wrist strap connected by a ground cord to a grounded workstation or computer chassis. Wrist straps are flexible straps with a minimum of 1 megohm ± 10 percent resistance in the ground cords. To provide proper ground, wear the strap snug against the skin.
- Use heel straps, toe straps, or boot straps at standing workstations. Wear the straps on both feet when standing on conductive floors or dissipating floor mats.
- Use conductive field service tools.
- Use a portable field service kit with a folding static-dissipating work mat.

If you do not have any of the suggested equipment for proper grounding, have an authorized reseller install the part.

For more information on static electricity or assistance with product installation, contact an authorized reseller.

Specifications

Environmental specifications

Specification	Value
Temperature range*	—
Operating	10°C to 35°C (50°F to 95°F)
Non-operating	-30°C to 60°C (-22°F to 140°F)
Relative humidity (noncondensing)**	—
Operating	10% to 90% @ 28°C (82.4°F)
Non-operating	5% to 95% @ 38.7°C (101.7°F)
Altitude†	—
Operating	3050 m (10,000 ft)
Non-operating	9144 m (30,000 ft)

* The following temperature conditions and limitations apply:

- All temperature ratings shown are for sea level.
- An altitude derating of 1°C per 304.8 m (1.8°F per 1,000 ft) up to 3048 m (10,000 ft) applies.
- No direct sunlight is allowed.
- The maximum permissible rate of change is 10°C/hr (18°F/hr).
- The type and number of options installed may reduce the upper temperature and humidity limits.
- Operating with a fan fault or above 30°C (86°F) may reduce system performance.

** Storage maximum humidity of 95% is based on a maximum temperature of 45°C (113°F).

†Maximum storage altitude corresponds to a minimum pressure of 70 kPa (10.1 psia).

Server blade specifications

Specification	Value
Height	5.08 cm (2.00 in)
Depth	50.65 cm (19.94 in)
Width	36.68 cm (14.44 in)
Weight (maximum)	7.54 kg (20.20 lb)
Weight (minimum)	10.11 kg (27.10 lb)

Support and other resources

Before you contact HP

Be sure to have the following information available before you call HP:

- Active Health System log
Download and have available an Active Health System log for 3 days before the failure was detected. For more information, see the *HP iLO 4 User Guide* or *HP Intelligent Provisioning User Guide* on the HP website (<http://www.hp.com/go/ilo/docs>).
- Onboard Administrator SHOW ALL report (for HP BladeSystem products only)
For more information on obtaining the Onboard Administrator SHOW ALL report, see the HP website (<http://h20000.www2.hp.com/bizsupport/TechSupport/Document.jsp?lang=en&cc=us&objectID=c02843807>).
- Technical support registration number (if applicable)
- Product serial number
- Product model name and number
- Product identification number
- Applicable error messages
- Add-on boards or hardware
- Third-party hardware or software
- Operating system type and revision level

HP contact information

For United States and worldwide contact information, see the Contact HP website (<http://www.hp.com/go/assistance>).

In the United States:

- To contact HP by phone, call 1-800-334-5144. For continuous quality improvement, calls may be recorded or monitored.
- If you have purchased a Care Pack (service upgrade), see the Support & Drivers website (<http://www8.hp.com/us/en/support-drivers.html>). If the problem cannot be resolved at the website, call 1-800-633-3600. For more information about Care Packs, see the HP website (<http://pro-aq-sama.houston.hp.com/services/cache/10950-0-0-225-121.html>).

Customer Self Repair

HP products are designed with many Customer Self Repair (CSR) parts to minimize repair time and allow for greater flexibility in performing defective parts replacement. If during the diagnosis period HP (or HP service

providers or service partners) identifies that the repair can be accomplished by the use of a CSR part, HP will ship that part directly to you for replacement. There are two categories of CSR parts:

- **Mandatory**—Parts for which customer self repair is mandatory. If you request HP to replace these parts, you will be charged for the travel and labor costs of this service.
- **Optional**—Parts for which customer self repair is optional. These parts are also designed for customer self repair. If, however, you require that HP replace them for you, there may or may not be additional charges, depending on the type of warranty service designated for your product.

NOTE: Some HP parts are not designed for customer self repair. In order to satisfy the customer warranty, HP requires that an authorized service provider replace the part. These parts are identified as "No" in the Illustrated Parts Catalog.

Based on availability and where geography permits, CSR parts will be shipped for next business day delivery. Same day or four-hour delivery may be offered at an additional charge where geography permits. If assistance is required, you can call the HP Technical Support Center and a technician will help you over the telephone. HP specifies in the materials shipped with a replacement CSR part whether a defective part must be returned to HP. In cases where it is required to return the defective part to HP, you must ship the defective part back to HP within a defined period of time, normally five (5) business days. The defective part must be returned with the associated documentation in the provided shipping material. Failure to return the defective part may result in HP billing you for the replacement. With a customer self repair, HP will pay all shipping and part return costs and determine the courier/carrier to be used.

For more information about HP's Customer Self Repair program, contact your local service provider. For the North American program, refer to the HP website (<http://www.hp.com/go/selfrepair>).

Réparation par le client (CSR)

Les produits HP comportent de nombreuses pièces CSR (Customer Self Repair = réparation par le client) afin de minimiser les délais de réparation et faciliter le remplacement des pièces défectueuses. Si pendant la période de diagnostic, HP (ou ses partenaires ou mainteneurs agréés) détermine que la réparation peut être effectuée à l'aide d'une pièce CSR, HP vous l'envoie directement. Il existe deux catégories de pièces CSR:

Obligatoire - Pièces pour lesquelles la réparation par le client est obligatoire. Si vous demandez à HP de remplacer ces pièces, les coûts de déplacement et main d'œuvre du service vous seront facturés.

Facultatif - Pièces pour lesquelles la réparation par le client est facultative. Ces pièces sont également conçues pour permettre au client d'effectuer lui-même la réparation. Toutefois, si vous demandez à HP de remplacer ces pièces, l'intervention peut ou non vous être facturée, selon le type de garantie applicable à votre produit.

REMARQUE: Certaines pièces HP ne sont pas conçues pour permettre au client d'effectuer lui-même la réparation. Pour que la garantie puisse s'appliquer, HP exige que le remplacement de la pièce soit effectué par un Mainteneur Agréé. Ces pièces sont identifiées par la mention "Non" dans le Catalogue illustré.

Les pièces CSR sont livrées le jour ouvré suivant, dans la limite des stocks disponibles et selon votre situation géographique. Si votre situation géographique le permet et que vous demandez une livraison le jour même ou dans les 4 heures, celle-ci vous sera facturée. Pour bénéficier d'une assistance téléphonique, appelez le Centre d'assistance technique HP. Dans les documents envoyés avec la pièce de rechange CSR, HP précise s'il est nécessaire de lui retourner la pièce défectueuse. Si c'est le cas, vous devez le faire dans le délai indiqué, généralement cinq (5) jours ouvrés. La pièce et sa documentation doivent être retournées dans l'emballage fourni. Si vous ne retournez pas la pièce défectueuse, HP se réserve le droit de vous facturer les coûts de remplacement. Dans le cas d'une pièce CSR, HP supporte l'ensemble des frais d'expédition et de retour, et détermine la société de courses ou le transporteur à utiliser.

Pour plus d'informations sur le programme CSR de HP, contactez votre Mainteneur Agréé local. Pour plus d'informations sur ce programme en Amérique du Nord, consultez le site Web HP (<http://www.hp.com/go/selfrepair>).

Riparazione da parte del cliente

Per abbreviare i tempi di riparazione e garantire una maggiore flessibilità nella sostituzione di parti difettose, i prodotti HP sono realizzati con numerosi componenti che possono essere riparati direttamente dal cliente (CSR, Customer Self Repair). Se in fase di diagnostica HP (o un centro di servizi o di assistenza HP) identifica il guasto come riparabile mediante un ricambio CSR, HP lo spedisce direttamente al cliente per la sostituzione. Vi sono due categorie di parti CSR:

Obbligatorie – Parti che devono essere necessariamente riparate dal cliente. Se il cliente ne affida la riparazione ad HP, deve sostenere le spese di spedizione e di manodopera per il servizio.

Opzionali – Parti la cui riparazione da parte del cliente è facoltativa. Si tratta comunque di componenti progettati per questo scopo. Se tuttavia il cliente ne richiede la sostituzione ad HP, potrebbe dover sostenere spese aggiuntive a seconda del tipo di garanzia previsto per il prodotto.

NOTA: alcuni componenti HP non sono progettati per la riparazione da parte del cliente. Per rispettare la garanzia, HP richiede che queste parti siano sostituite da un centro di assistenza autorizzato. Tali parti sono identificate da un "No" nel Catalogo illustrato dei componenti.

In base alla disponibilità e alla località geografica, le parti CSR vengono spedite con consegna entro il giorno lavorativo seguente. La consegna nel giorno stesso o entro quattro ore è offerta con un supplemento di costo solo in alcune zone. In caso di necessità si può richiedere l'assistenza telefonica di un addetto del centro di supporto tecnico HP. Nel materiale fornito con una parte di ricambio CSR, HP specifica se il cliente deve restituire dei componenti. Qualora sia richiesta la resa ad HP del componente difettoso, lo si deve spedire ad HP entro un determinato periodo di tempo, generalmente cinque (5) giorni lavorativi. Il componente difettoso deve essere restituito con la documentazione associata nell'imballo di spedizione fornito. La mancata restituzione del componente può comportare la fatturazione del ricambio da parte di HP. Nel caso di riparazione da parte del cliente, HP sostiene tutte le spese di spedizione e resa e sceglie il corriere/vettore da utilizzare.

Per ulteriori informazioni sul programma CSR di HP contattare il centro di assistenza di zona. Per il programma in Nord America fare riferimento al sito Web HP (<http://www.hp.com/go/selfrepair>).

Customer Self Repair

HP Produkte enthalten viele CSR-Teile (Customer Self Repair), um Reparaturzeiten zu minimieren und höhere Flexibilität beim Austausch defekter Bauteile zu ermöglichen. Wenn HP (oder ein HP Servicepartner) bei der Diagnose feststellt, dass das Produkt mithilfe eines CSR-Teils repariert werden kann, sendet Ihnen HP dieses Bauteil zum Austausch direkt zu. CSR-Teile werden in zwei Kategorien unterteilt:

Zwingend – Teile, für die das Customer Self Repair-Verfahren zwingend vorgegeben ist. Wenn Sie den Austausch dieser Teile von HP vornehmen lassen, werden Ihnen die Anfahrt- und Arbeitskosten für diesen Service berechnet.

Optional – Teile, für die das Customer Self Repair-Verfahren optional ist. Diese Teile sind auch für Customer Self Repair ausgelegt. Wenn Sie jedoch den Austausch dieser Teile von HP vornehmen lassen möchten, können bei diesem Service je nach den für Ihr Produkt vorgesehenen Garantiebedingungen zusätzliche Kosten anfallen.

HINWEIS: Einige Teile sind nicht für Customer Self Repair ausgelegt. Um den Garantieanspruch des Kunden zu erfüllen, muss das Teil von einem HP Servicepartner ersetzt werden. Im illustrierten Teilekatalog sind diese Teile mit „No“ bzw. „Nein“ gekennzeichnet.

CSR-Teile werden abhängig von der Verfügbarkeit und vom Lieferziel am folgenden Geschäftstag geliefert. Für bestimmte Standorte ist eine Lieferung am selben Tag oder innerhalb von vier Stunden gegen einen Aufpreis verfügbar. Wenn Sie Hilfe benötigen, können Sie das HP technische Support Center anrufen und sich von einem Mitarbeiter per Telefon helfen lassen. Den Materialien, die mit einem CSR-Ersatzteil geliefert werden, können Sie entnehmen, ob das defekte Teil an HP zurückgeschickt werden muss. Wenn es erforderlich ist, das defekte Teil an HP zurückzuschicken, müssen Sie dies innerhalb eines vorgegebenen Zeitraums tun, in der Regel innerhalb von fünf (5) Geschäftstagen. Das defekte Teil muss mit der zugehörigen Dokumentation in der Verpackung zurückgeschickt werden, die im Lieferumfang enthalten ist. Wenn Sie das defekte Teil nicht zurückschicken, kann HP Ihnen das Ersatzteil in Rechnung stellen. Im Falle von Customer Self Repair kommt HP für alle Kosten für die Lieferung und Rücksendung auf und bestimmt den Kurier-/Frachtdienst.

Weitere Informationen über das HP Customer Self Repair Programm erhalten Sie von Ihrem Servicepartner vor Ort. Informationen über das CSR-Programm in Nordamerika finden Sie auf der HP Website unter (<http://www.hp.com/go/selfrepair>).

Reparaciones del propio cliente

Los productos de HP incluyen muchos componentes que el propio usuario puede reemplazar (*Customer Self Repair*, CSR) para minimizar el tiempo de reparación y ofrecer una mayor flexibilidad a la hora de realizar sustituciones de componentes defectuosos. Si, durante la fase de diagnóstico, HP (o los proveedores o socios de servicio de HP) identifica que una reparación puede llevarse a cabo mediante el uso de un componente CSR, HP le enviará dicho componente directamente para que realice su sustitución. Los componentes CSR se clasifican en dos categorías:

- **Obligatorio:** componentes para los que la reparación por parte del usuario es obligatoria. Si solicita a HP que realice la sustitución de estos componentes, tendrá que hacerse cargo de los gastos de desplazamiento y de mano de obra de dicho servicio.
- **Opcional:** componentes para los que la reparación por parte del usuario es opcional. Estos componentes también están diseñados para que puedan ser reparados por el usuario. Sin embargo, si precisa que HP realice su sustitución, puede o no conllevar costes adicionales, dependiendo del tipo de servicio de garantía correspondiente al producto.

NOTA: Algunos componentes no están diseñados para que puedan ser reparados por el usuario. Para que el usuario haga valer su garantía, HP pone como condición que un proveedor de servicios autorizado realice la sustitución de estos componentes. Dichos componentes se identifican con la palabra "No" en el catálogo ilustrado de componentes.

Según la disponibilidad y la situación geográfica, los componentes CSR se enviarán para que lleguen a su destino al siguiente día laborable. Si la situación geográfica lo permite, se puede solicitar la entrega en el mismo día o en cuatro horas con un coste adicional. Si precisa asistencia técnica, puede llamar al Centro de asistencia técnica de HP y recibirá ayuda telefónica por parte de un técnico. Con el envío de materiales para la sustitución de componentes CSR, HP especificará si los componentes defectuosos deberán devolverse a HP. En aquellos casos en los que sea necesario devolver algún componente a HP, deberá hacerlo en el periodo de tiempo especificado, normalmente cinco días laborables. Los componentes defectuosos deberán devolverse con toda la documentación relacionada y con el embalaje de envío. Si no enviara el componente defectuoso requerido, HP podrá cobrarle por el de sustitución. En el caso de todas

sustituciones que lleve a cabo el cliente, HP se hará cargo de todos los gastos de envío y devolución de componentes y escogerá la empresa de transporte que se utilice para dicho servicio.

Para obtener más información acerca del programa de Reparaciones del propio cliente de HP, póngase en contacto con su proveedor de servicios local. Si está interesado en el programa para Norteamérica, visite la página web de HP siguiente (<http://www.hp.com/go/selfrepair>).

Customer Self Repair

Veel onderdelen in HP producten zijn door de klant zelf te repareren, waardoor de reparatieduur tot een minimum beperkt kan blijven en de flexibiliteit in het vervangen van defecte onderdelen groter is. Deze onderdelen worden CSR-onderdelen (Customer Self Repair) genoemd. Als HP (of een HP Service Partner) bij de diagnose vaststelt dat de reparatie kan worden uitgevoerd met een CSR-onderdeel, verzendt HP dat onderdeel rechtstreeks naar u, zodat u het defecte onderdeel daarmee kunt vervangen. Er zijn twee categorieën CSR-onderdelen:

Verplicht: Onderdelen waarvoor reparatie door de klant verplicht is. Als u HP verzoekt deze onderdelen voor u te vervangen, worden u voor deze service reiskosten en arbeidsloon in rekening gebracht.

Optioneel: Onderdelen waarvoor reparatie door de klant optioneel is. Ook deze onderdelen zijn ontworpen voor reparatie door de klant. Als u echter HP verzoekt deze onderdelen voor u te vervangen, kunnen daarvoor extra kosten in rekening worden gebracht, afhankelijk van het type garanteservice voor het product.

OPMERKING: Sommige HP onderdelen zijn niet ontwikkeld voor reparatie door de klant. In verband met de garantievoorwaarden moet het onderdeel door een geautoriseerde Service Partner worden vervangen. Deze onderdelen worden in de geïllustreerde onderdelencatalogus aangemerkt met "Nee".

Afhankelijk van de leverbaarheid en de locatie worden CSR-onderdelen verzonden voor levering op de eerstvolgende werkdag. Levering op dezelfde dag of binnen vier uur kan tegen meerkosten worden aangeboden, indien dit mogelijk is gezien de locatie. Indien assistentie gewenst is, belt u een HP Service Partner om via de telefoon technische ondersteuning te ontvangen. HP vermeldt in de documentatie bij het vervangende CSR-onderdeel of het defecte onderdeel aan HP moet worden geretourneerd. Als het defecte onderdeel aan HP moet worden teruggezonden, moet u het defecte onderdeel binnen een bepaalde periode, gewoonlijk vijf (5) werkdagen, retourneren aan HP. Het defecte onderdeel moet met de bijbehorende documentatie worden geretourneerd in het meegeleverde verpakkingsmateriaal. Als u het defecte onderdeel niet terugzendt, kan HP u voor het vervangende onderdeel kosten in rekening brengen. Bij reparatie door de klant betaalt HP alle verzendkosten voor het vervangende en geretourneerde onderdeel en kiest HP zelf welke koerier/transportonderneming hiervoor wordt gebruikt.

Neem contact op met een Service Partner voor meer informatie over het Customer Self Repair programma van HP. Informatie over Service Partners vindt u op de HP website (<http://www.hp.com/go/selfrepair>).

Reparo feito pelo cliente

Os produtos da HP são projetados com muitas peças para reparo feito pelo cliente (CSR) de modo a minimizar o tempo de reparo e permitir maior flexibilidade na substituição de peças com defeito. Se, durante o período de diagnóstico, a HP (ou fornecedores/parceiros de serviço da HP) concluir que o reparo pode ser efetuado pelo uso de uma peça CSR, a peça de reposição será enviada diretamente ao cliente. Existem duas categorias de peças CSR:

Obrigatória – Peças cujo reparo feito pelo cliente é obrigatório. Se desejar que a HP substitua essas peças, serão cobradas as despesas de transporte e mão-de-obra do serviço.

Opcional – Peças cujo reparo feito pelo cliente é opcional. Essas peças também são projetadas para o reparo feito pelo cliente. No entanto, se desejar que a HP as substitua, pode haver ou não a cobrança de taxa adicional, dependendo do tipo de serviço de garantia destinado ao produto.

OBSERVAÇÃO: Algumas peças da HP não são projetadas para o reparo feito pelo cliente. A fim de cumprir a garantia do cliente, a HP exige que um técnico autorizado substitua a peça. Essas peças estão identificadas com a marca "No" (Não), no catálogo de peças ilustrado.

Conforme a disponibilidade e o local geográfico, as peças CSR serão enviadas no primeiro dia útil após o pedido. Onde as condições geográficas permitirem, a entrega no mesmo dia ou em quatro horas pode ser feita mediante uma taxa adicional. Se precisar de auxílio, entre em contato com o Centro de suporte técnico da HP para que um técnico o ajude por telefone. A HP especifica nos materiais fornecidos com a peça CSR de reposição se a peça com defeito deve ser devolvida à HP. Nos casos em que isso for necessário, é preciso enviar a peça com defeito à HP dentro do período determinado, normalmente cinco (5) dias úteis. A peça com defeito deve ser enviada com a documentação correspondente no material de transporte fornecido. Caso não o faça, a HP poderá cobrar a reposição. Para as peças de reparo feito pelo cliente, a HP paga todas as despesas de transporte e de devolução da peça e determina a transportadora/serviço postal a ser utilizado.

Para obter mais informações sobre o programa de reparo feito pelo cliente da HP, entre em contato com o fornecedor de serviços local. Para o programa norte-americano, visite o site da HP (<http://www.hp.com/go/selfrepair>).

顧客自己修理保証サービス

修理時間を短縮し、故障部品の交換における高い柔軟性を確保するために、HP製品には多数の顧客自己修理（CSR）部品があります。診断の際に、CSR部品を使用すれば修理ができるとHP（HPまたはHP正規保守代理店）が判断した場合、HPはその部品を直接、お客様に発送し、お客様に交換していただきます。CSR部品には以下の2通りがあります。

- **必須**-顧客自己修理が必須の部品。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、その修理サービスに関する交通費および人件費がお客様に請求されます。
- **任意**-顧客自己修理が任意である部品。この部品も顧客自己修理用です。当該部品について、もしもお客様がHPに交換作業を依頼される場合には、お買い上げの製品に適用される保証サービス内容の範囲内においては、別途費用を負担していただくことなく保証サービスを受けることができます。

注：HP製品の一部の部品は、顧客自己修理用ではありません。製品の保証を継続するためには、HPまたはHP正規保守代理店による交換作業が必須となります。部品カタログには、当該部品が顧客自己修理除外品である旨が記載されています。

部品供給が可能な場合、地域によっては、CSR部品を翌営業日に届くように発送します。また、地域によっては、追加費用を負担いただくことにより同日または4時間以内に届くように発送することも可能な場合があります。サポートが必要なときは、HPの修理受付窓口に電話していただければ、技術者が電話でアドバイスします。交換用のCSR部品または同梱物には、故障部品をHPに返送する必要があるかどうかが表示されています。故障部品をHPに返送する必要がある場合は、指定期限内（通常は5営業日以内）に故障部品をHPに返送してください。故障部品を返送する場合は、届いた時の梱包箱に関連書類とともに入れてください。故障部品を返送しない場合、HPから部品費用が請求されます。顧客自己修理の際には、HPは送料および部品返送費を全額負担し、使用する宅配便会社や運送会社を指定します。

客户自行维修

HP 产品提供许多客户自行维修 (CSR) 部件，以尽可能缩短维修时间和在更换缺陷部件方面提供更大的灵活性。如果在诊断期间 HP（或 HP 服务提供商或服务合作伙伴）确定可以通过使用 CSR 部件完成维修，HP 将直接把该部件发送给您进行更换。有两类 CSR 部件：

- **强制性的** — 要求客户必须自行维修的部件。如果您请求 HP 更换这些部件，则必须为该服务支付差旅费和人工费用。
- **可选的** — 客户可以选择是否自行维修的部件。这些部件也是为客户自行维修设计的。不过，如果您要求 HP 为您更换这些部件，则根据您的产品指定的保修服务类型，HP 可能收取或不再收取任何附加费用。

注：某些 HP 部件的设计并未考虑客户自行维修。为了满足客户保修的需要，HP 要求授权服务提供商更换相关部件。这些部件在部件图解目录中标记为“否”。

CSR 部件将在下一个工作日发运（取决于备货情况和允许的地理范围）。在允许的地理范围内，可在当天或四小时内发运，但要收取额外费用。如果需要帮助，您可以致电 HP 技术支持中心，将会有技术人员通过电话为您提供帮助。HP 会在随更换的 CSR 部件发运的材料中指明是否必须将有缺陷的部件返还给 HP。如果要求您将有缺陷的部件返还给 HP，那么您必须在指定期限内（通常是五 (5) 个工作日）将缺陷部件发给 HP。有缺陷的部件必须随所提供的发运材料中的相关文件一起返还。如果未能送还有缺陷的部件，HP 可能会要求您支付更换费用。客户自行维修时，HP 将承担所有相关运输和部件返回费用，并指定快递商/承运商。

有关 HP 客户自行维修计划的详细信息，请与您当地的服务提供商联系。有关北美地区的计划，请访问 HP 网站 (<http://www.hp.com/go/selfrepair>)。

客戶自行維修

HP 產品設計了許多「客戶自行維修」(CSR) 的零件以減少維修時間，並且使得更換瑕疵零件時能有更大的彈性。如果在診斷期間 HP (或 HP 服務供應商或維修夥伴) 辨認出此項維修工作可以藉由使用 CSR 零件來完成，則 HP 將直接寄送該零件給您作更換。CSR 零件分為兩種類別：

- **強制的** — 客戶自行維修所使用的零件是強制性的。如果您要求 HP 更換這些零件，HP 將會向您收取此服務所需的外出費用與勞動成本。
- **選購的** — 客戶自行維修所使用的零件是選購的。這些零件也設計用於客戶自行維修之用。不過，如果您要求 HP 為您更換，則可能需要也可能不需要負擔額外的費用，端視針對此產品指定的保固服務類型而定。

備註：某些 HP 零件沒有消費者可自行維修的設計。為符合客戶保固，HP 需要授權的服務供應商更換零件。這些零件在圖示的零件目錄中，被標示為「否」。

基於材料取得及環境允許的情況下，CSR 零件將於下一個工作日以快遞寄送。在環境的允許下當天或四小時內送達，則可能需要額外的費用。若您需要協助，可致電「HP 技術支援中心」，會有一位技術人員透過電話來協助您。不論損壞的零件是否必須退回，HP 皆會在與 CSR 替換零件一起運送的材料中註明。若要將損壞的零件退回 HP，您必須在指定的一段時間內（通常為五 (5) 個工作天），將損壞的零件寄回 HP。損壞的零件必須與寄送資料中隨附的相關技術文件一併退還。如果無法退還損壞的零件，HP 可能要向您收取替換費用。針對客戶自行維修情形，HP 將負責所有運費及零件退還費用並指定使用何家快遞/貨運公司。

如需 HP 的「客戶自行維修」方案詳細資訊，請連絡您當地的服務供應商。至於北美方案，請參閱 HP 網站 (<http://www.hp.com/go/selfrepair>)。

고객 셀프 수리

HP 제품은 수리 시간을 최소화하고 결함이 있는 부품 교체 시 더욱 융통성을 발휘할 수 있도록 하기 위해 고객 셀프 수리(CSR) 부품을 다량 사용하여 설계되었습니다. 진단 기간 동안 HP(또는 HP 서비스 공급업체 또는 서비스 협력업체)에서 CSR 부품을 사용하여 수리가 가능하다고 판단되면 HP는 해당 부품을 바로 사용자에게 보내어 사용자가 교체할 수 있도록 합니다. CSR 부품에는 두 가지 종류가 있습니다.

- **고객 셀프 수리가 의무 사항인 필수 부품.** 사용자가 HP에 이 부품의 교체를 요청할 경우 이 서비스에 대한 출장비 및 작업비가 청구됩니다.
- **고객 셀프 수리가 선택 사항인 부품.** 이 부품들도 고객 셀프 수리가 가능하도록 설계되었습니다. 하지만 사용자가 HP에 이 부품의 교체를 요청할 경우 사용자가 구입한 제품에 해당하는 보증 서비스 유형에 따라 추가 비용 없이 교체가 가능할 수 있습니다.

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CSR 부품은 재고 상태와 지리적 조건이 허용하는 경우 다음 영업일 납품이 가능하도록 배송이 이루어집니다. 지리적 조건이 허용하는 경우 추가 비용이 청구되는 조건으로 당일 또는 4시간 배송이 가능할 수도 있습니다. 도움이 필요하시면 HP 기술 지원 센터로 전화하십시오. 전문 기술자가 전화로 도움을 줄 것입니다. HP는 결함이 발생한 부품을 HP로 반환해야 하는지 여부를 CSR 교체 부품과 함께 배송된 자료에 지정합니다. 결함이 발생한 부품을 HP로 반환해야 하는 경우에는 지정된 기간 내(통상 영업일 기준 5일)에 HP로 반환해야 합니다. 이 때 결함이 발생한 부품은 제공된 포장 재료에 넣어 관련 설명서와 함께 반환해야 합니다. 결함이 발생한 부품을 반환하지 않는 경우 HP가 교체 부품에 대해 비용을 청구할 수 있습니다. 고객 셀프 수리의 경우, HP는 모든 운송 및 부품 반환 비용을 부담하며 이용할 운송업체 및 택배 서비스를 결정합니다.

HP 고객 셀프 수리 프로그램에 대한 자세한 내용은 가까운 서비스 제공업체에 문의하십시오. 북미 지역의 프로그램에 대해서는 HP 웹 사이트(<http://www.hp.com/go/selfrepair>)를 참조하십시오.

Acronyms and abbreviations

ABEND

abnormal end

ACU

Array Configuration Utility

ADM

Advanced Data Mirroring

AMP

Advanced Memory Protection

ASR

Automatic Server Recovery

FBWC

flash-backed write cache

iLO

Integrated Lights-Out

IML

Integrated Management Log

LRDIMM

load reduced dual in-line memory module

ORCA

Option ROM Configuration for Arrays

POST

Power-On Self Test

PXE

preboot execution environment

RBSU

ROM-Based Setup Utility

RDIMM

registered dual in-line memory module

SAS

serial attached SCSI

SATA

serial ATA

SIM

Systems Insight Manager

UDIMM

unregistered dual in-line memory module

UID

unit identification

USB

universal serial bus

VCA

Version Control Agent

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Index

A

- access panel 14
- acoustics statement for Germany 69
- ACU (Array Configuration Utility) 50, 58
- Advanced ECC memory 36, 37, 57
- AMP (Advanced Memory Protection) 57
- AMP modes 57
- Array Configuration Utility (ACU) 58
- ASR (Automatic Server Recovery) 59
- authorized reseller 73
- auto-configuration process 56
- Automatic Server Recovery (ASR) 59

B

- Basic Input/Output System (BIOS) 50, 59
- batteries, replacing 63, 69
- battery 8, 63, 69
- battery disposal 66, 69
- battery replacement notice 63, 69
- before you contact HP 73
- BIOS (Basic Input/Output System) 50, 59
- BIOS upgrade 50, 59
- blade blank 19, 25
- boot options 57
- BSMI notice 67
- buttons 6

C

- cables 46, 47, 48, 49, 65
- cables, FCC compliance 65
- cabling 46, 47
- Canadian notices 65
- capacitor pack 17
- Change Control 61
- change control and proactive notification 61
- Chinese notice 68
- class A equipment 64
- class B equipment 64
- compliance 64
- components 6
- components, identification 6
- configuration 26

- configuration of system 26, 50
- configuration, completing 26
- configuring AMP modes 57
- connecting to the network 24
- connectors 6
- contact information 73
- contacting HP 73
- CSR (customer self repair) 73
- customer self repair (CSR) 73

D

- Declaration of Conformity 65
- default settings 36
- device bay blank 25
- device bay shelf, removing 20, 21
- diagnosing problems 62
- diagnostic tools 50, 53, 59
- diagnostics utility 53
- dimensions, server 72
- DIMM baffles 14, 15, 16
- DIMM identification 35
- DIMM installation guidelines 37
- DIMM population guidelines 37
- DIMM slot locations 8, 9
- DIMM tool 10, 38
- DIMMs 8, 34, 38
- DIMMs, single- and dual-rank 34
- disposal, battery 66, 69
- disposal, waste 66
- documentation 83
- downloading files 73
- drivers 60
- drives 7, 14, 27
- drives, installing 27
- drives, removing 14

E

- electrostatic discharge 71
- enabling the Trusted Platform Module 45
- enabling, Trusted Platform Module (TPM) 45
- enclosure, installing 19
- environmental specifications 72
- Erase Utility 50, 53

error messages 62
European Union notice 66
European Union regulatory notice 66

F

FBWC capacitor cabling 46
FBWC capacitor pack 39, 46
FBWC procedures 17
FCC (Federal Communications Commission)
notice 64, 65
FCC rating label 64
features 6, 58
Federal Communications Commission (FCC)
notice 64, 65
firmware 61
firmware update 55, 61
firmware upgrade utility, troubleshooting 62
firmware, updating 55, 61
flash-backed write cache capacitor pack 46
front panel components 6
front panel LEDs 6
front panel/drive cage assembly 16
full-height device bay blank, creating 25

G

grounding methods 71

H

hard drive backplane connector 8
hard drive LEDs 7
hard drives, determining status of 7
hardware options 27
hardware options installation 27
health driver 59
health LEDs 6
heatsink 28
help resources 73
HP contact information 73
HP Insight Diagnostics 53
HP Insight Diagnostics survey functionality 53
HP Insight Remote Support software 54
HP Service Pack for ProLiant 50, 55
HP Smart memory 33
HP Smart Update Manager overview 50, 55
HP technical support 73
HP website 73
HP, contacting 73

I

identification number 64
iLO (Integrated Lights-Out) 12, 50, 51, 52
IML (Integrated Management Log) 50, 52
Insight Diagnostics 53, 60
installation, enclosure 19
installation, server blade 24
installation, server options 27
installing hardware 27
installing server blade options 27
installing server options 27
Integrated Lights-Out (iLO) 12, 50
Integrated Management Log (IML) 52
interconnect bay numbering 23
interconnect modules 22
interconnect modules, installing 22
internal USB connector 8

J

Japanese notice 67

K

Korean notices 67

L

laser compliance 68
laser devices 68
LED, health 6
LED, power button 6
LED, system power 6
LEDs 6, 7
LEDs, front panel 7
LEDs, hard drive 7
LEDs, NIC 6
LEDs, troubleshooting 62
LEDs, unit identification (UID) 6
local media devices, accessing 49
lockstep memory 36, 37

M

maintenance guidelines 60
memory 32, 34, 35, 36
memory configurations 35, 36
memory options 27, 32
memory subsystem architecture 33
memory, Advanced ECC 36, 57
memory, configuring 35, 36
memory, lockstep 36, 37

memory, online spare 36, 57
mezzanine card 40
mezzanine connectors 8, 9
modifications, FCC notice 65

N

network connections 24
NIC (network interface card) 8

O

online spare memory 36, 37, 57
operating system version support 61
operating systems 61
operating systems supported 61
operations 12
Option ROM Configuration for Arrays (ORCA) 50, 59
options 24, 50
options installation 24, 27
ORCA (Option ROM Configuration for Arrays) 50, 59

P

passwords 44
phone numbers 73
population order, memory 37, 38
powering down 12
preparation procedures 12
pro-active notification 61
problem diagnosis 62
processors 8, 28
Product ID 57

R

RBSU (ROM-Based Setup Utility) 50, 55, 56, 57
RBSU configuration 56
recovery key 44
redundant ROM 60
regulatory compliance identification numbers 64
regulatory compliance notices 64, 66, 69
removing the access panel 14
removing the server blade 13
required information 73
resources 73
retaining the recovery key/password 44
ROM redundancy 60
ROM-Based Setup Utility (RBSU) 45, 55
ROMPaq utility 50, 59, 60

S

safety considerations 60
safety information 60
screwdriver, T-15 Torx 10
scripted installation 54
serial connector 10
serial label pull tab 6
serial number 57
series number 64
server blade options, installing 27
server features and options 27
server options, installing 27
server specifications 72
servers, setup and configuration 19
Service Packs 55
setup 19, 22
Smart Update Firmware DVD 52
Smart Update Manager 50, 55
specifications 50, 72
specifications, environmental 72
SPP 55
standards 64
static electricity 71
support 73
supported operating systems 61
supported servers 62
supported targets 62
switches, interconnect 22
system board battery 8, 69
system board components 8
system board thumbscrews 8
system configuration settings 60
System Erase Utility 53
system maintenance switch 8
system, keeping current 60

T

T-15 Torx screwdriver 10
Taiwan battery recycling notice 69
technical support 73
telephone numbers 73
tool locations 10
tool, DIMM 10
tools 10
Torx screwdriver 10
TPM (Trusted Platform Module) 42, 44, 45
troubleshooting 62
troubleshooting resources 62
troubleshooting, firmware upgrade utility 62

Trusted Platform Module (TPM) 42, 43, 44, 45

U

Ukraine notice 68

updating the system ROM 60

USB connectors 10

USB devices 48, 49

USB support 59

utilities 50, 58

utilities, deployment 50, 54, 55

V

Version Control 61

Version Control Agent (VCA) 61

Version Control Repository Manager (VCRM) 61

video connector cabling 10

Vietnam compliance marking notice 68

W

website, HP 73

weight 72